Modeling and Design of Multiwinding Magnetics for High Frequency Power Electronics

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High Frequency Magnetics Workshop, 2020

PRINCETON POWERLAB

We Need Better Magnetics

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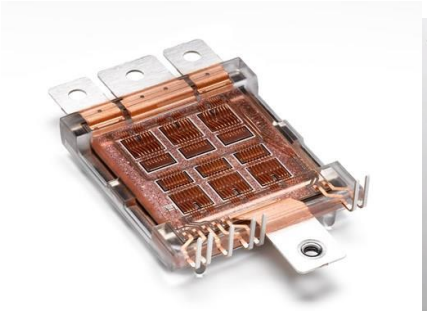
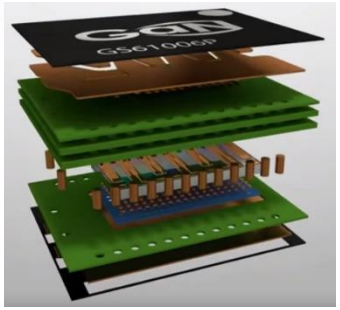
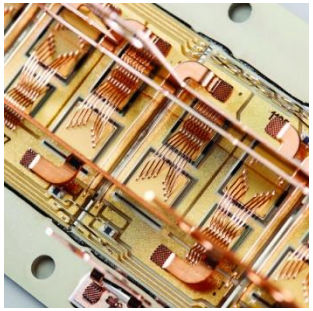
- **Breakthroughs in semiconductor devices (SiC and GaN)**



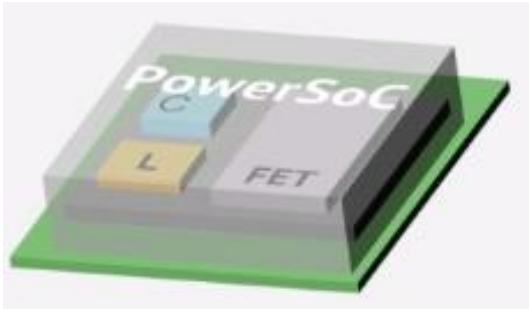
SiC modules



GaN Switches

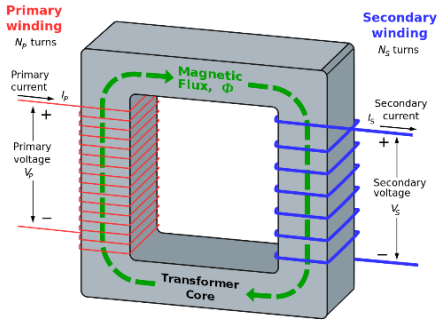


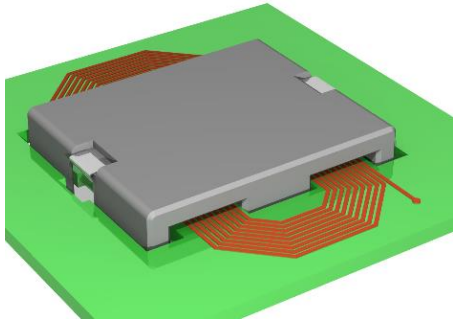
IGBT Modules

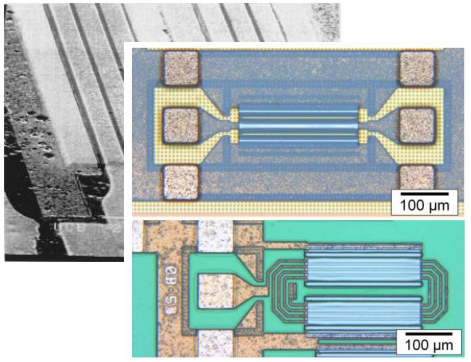


Power SoC

- **Magnetics are lagging behind**



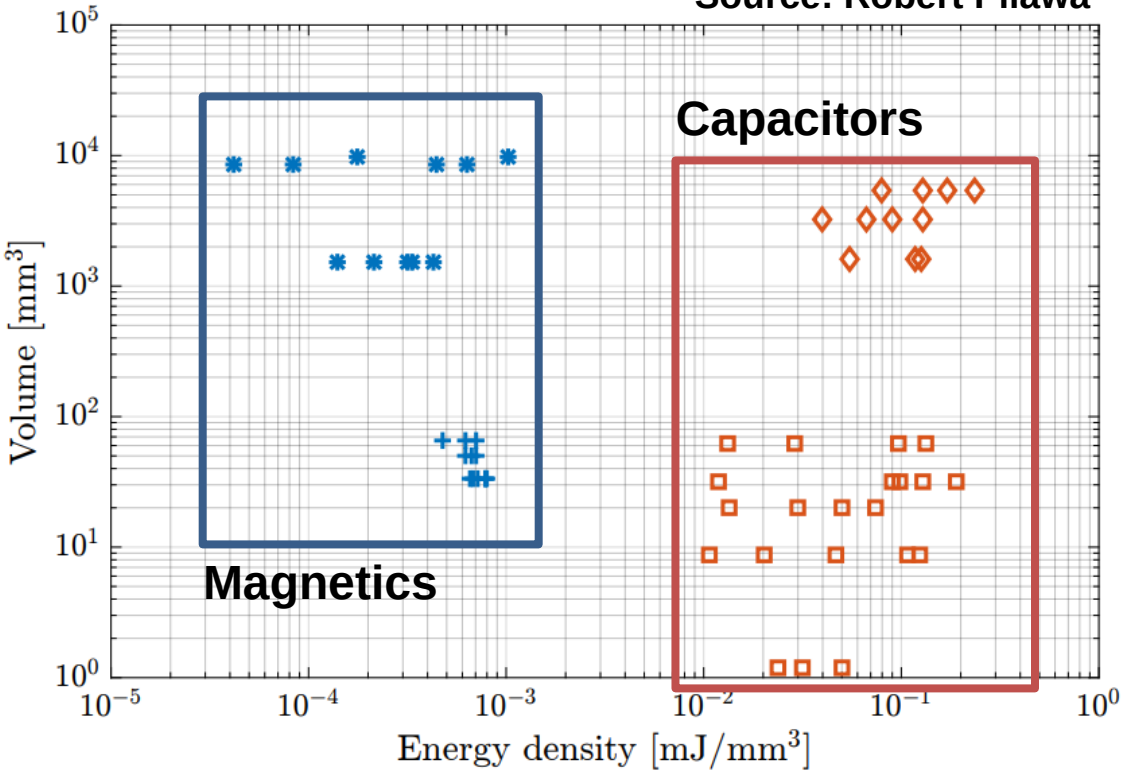




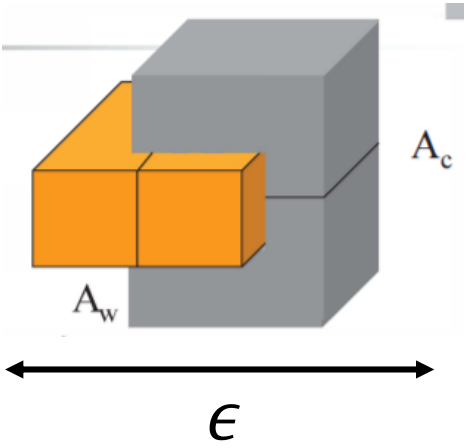
- L. Daniel, “Design of microfabricated inductors”, *IEEE Trans. Power Electron., 1999*
- D.S. Gardner, “Review of on-chip inductor structures with magnetic films”, *IEEE Trans. Magn., 2009*

Energy Density vs. Functionality

Source: Robert Pilawa



Source: Charles Sullivan



$$VA \propto \epsilon^4$$

Linear scaling factor

- Capacitors win in energy density
- Larger magnetics has better figure-of-merits
- Magnetics win in functionality
- **Multi-winding, multi-leg, multi-functional magnetics @ high frequency**

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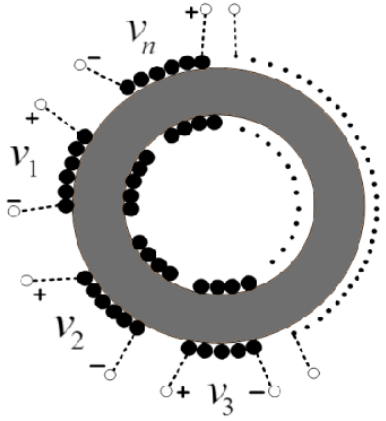
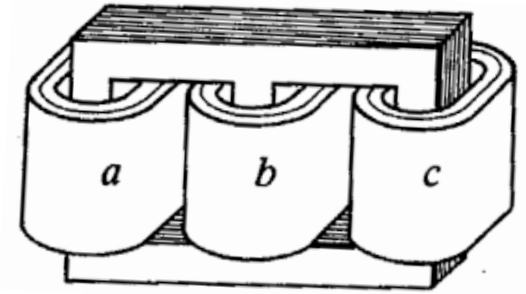
Single Purpose Magnetics

Multiwinding Magnetics



Multileg Magnetics



The "Integrated Magnetics" Concept

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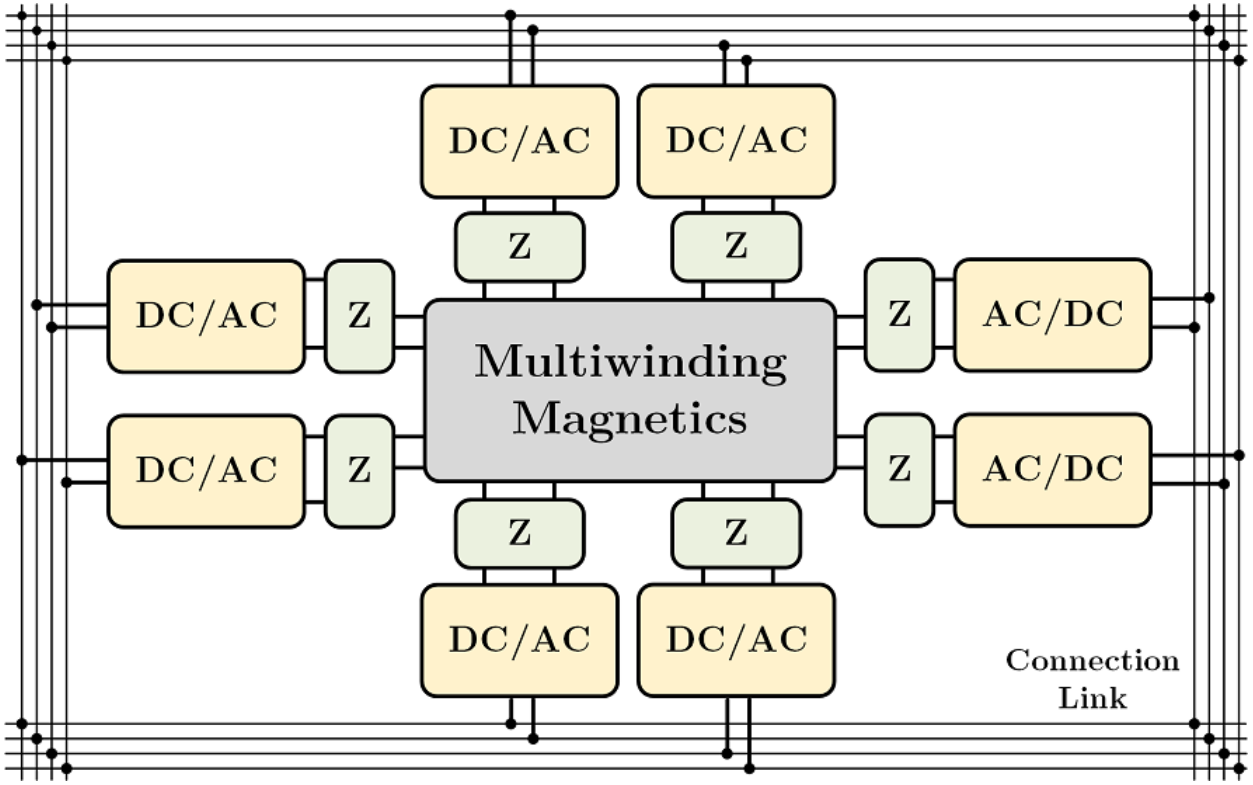
The "integrated magnetics" concept started from 1980s'



1980s

Zero-ripple Cuk

1990s

Multiphase Buck

2000s

Integ. EMI Filter

2010s

Resonant

Need tools and methods to design for high frequencies

Multi-Winding Magnetics: Two Categories

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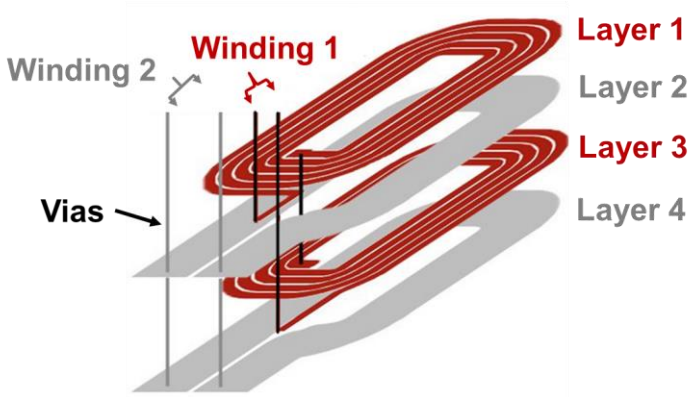
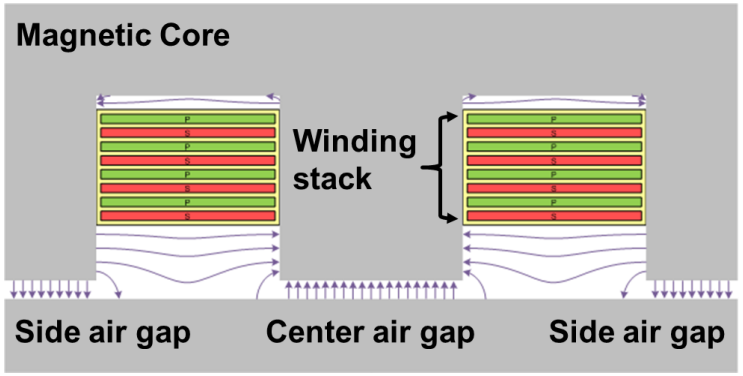
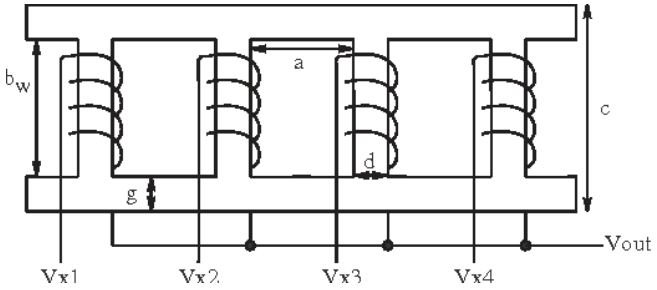
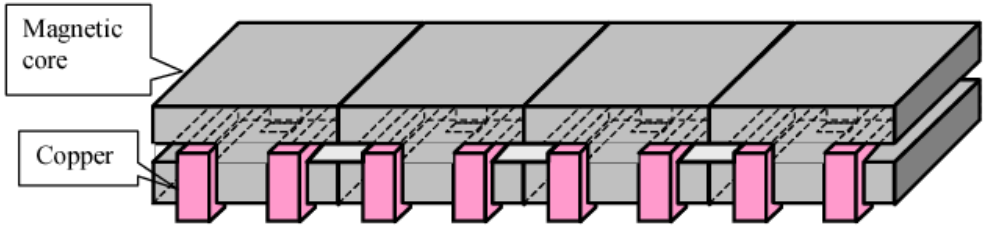
- Multiple windings couple to a single magnetic linkage





- Multiple windings couple to multiple magnetic linkages





- M. Chen, "A Systematic Approach to Modeling Impedances and Current Distribution in Planar Magnetics," TPEL 2016
- J. Li et al., "Using coupled inductors to enhance transient performance of multi-phase buck converters," APEC 2004

Design Options for Planar Magnetics

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1. What is the optimal way to interleave many layers?

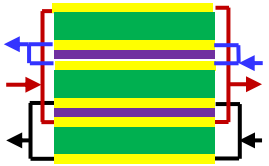
Alternating interleaved

1 & 3 as primary
2 & 4 as secondary

Symmetric interleaved

1 & 4 as primary
2 & 3 as secondary

More complicated?



……?

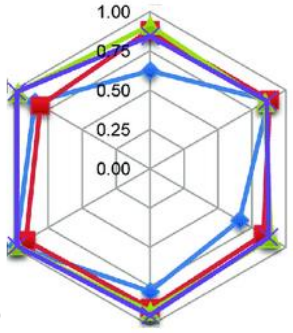
2. What are the optimal winding stack and winding spacing?

Thin Middle Spacing

Thick Middle Spacing

3. Multi-object optimization problem

1) Interleaving options?
2) Materials?
3) Geometry?
4) Size?
5) Efficiency?
6) Coupling coefficient?



Two Commonly Shared Assumptions

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Every model starts from assumptions …

(1) MQS assumption

- Assume $\frac{\partial E}{\partial t} = 0.$
- Applicable when the wavelength is much longer than the device size (usually lower than ~100MHz).

Magneto-Quasi-Static Maxwell's equations

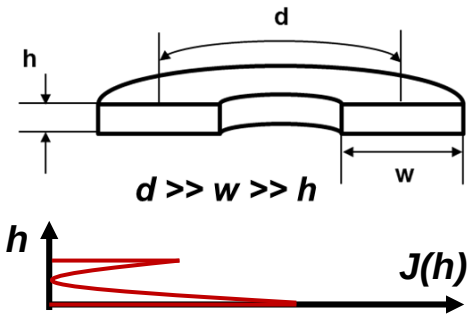
$$\begin{cases} \nabla E = \frac{\rho}{\varepsilon_0} \\ \nabla B = 0 \\ \nabla \times E = -\frac{\partial B}{\partial t} \\ \nabla \times B = \mu_0 (J + \varepsilon_0 \frac{\partial E}{\partial t}) \end{cases}$$

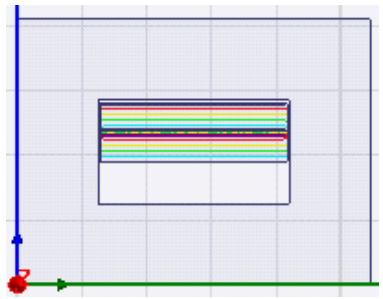
Ignore the time evolution of the electric field

(2) 1-D assumption

- Fields vary only along the thickness direction.
- Applicable when the flux is guided by the magnetic core.

Magnetic core guides the flux





Skin and proximity effects change current distribution

Wave Propagation in Planar Windings

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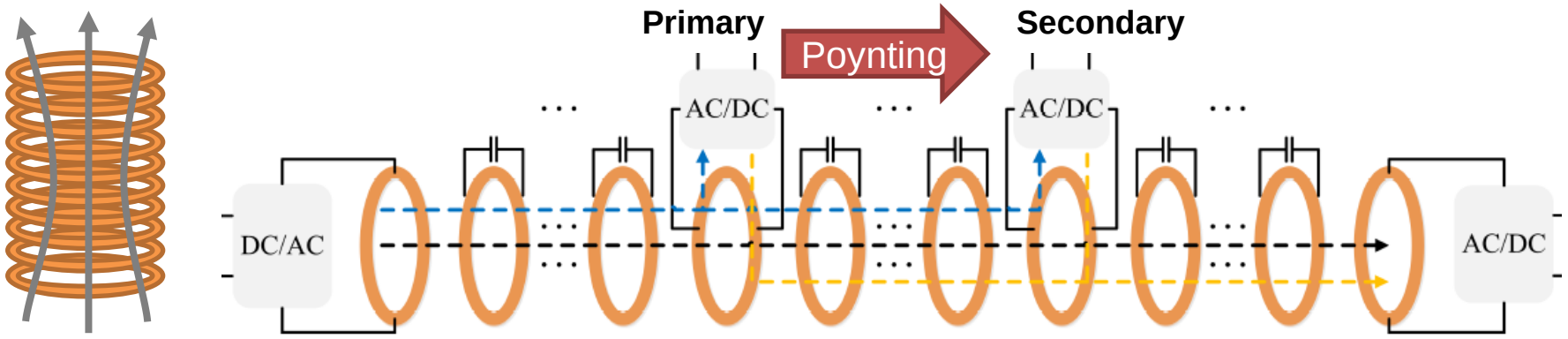
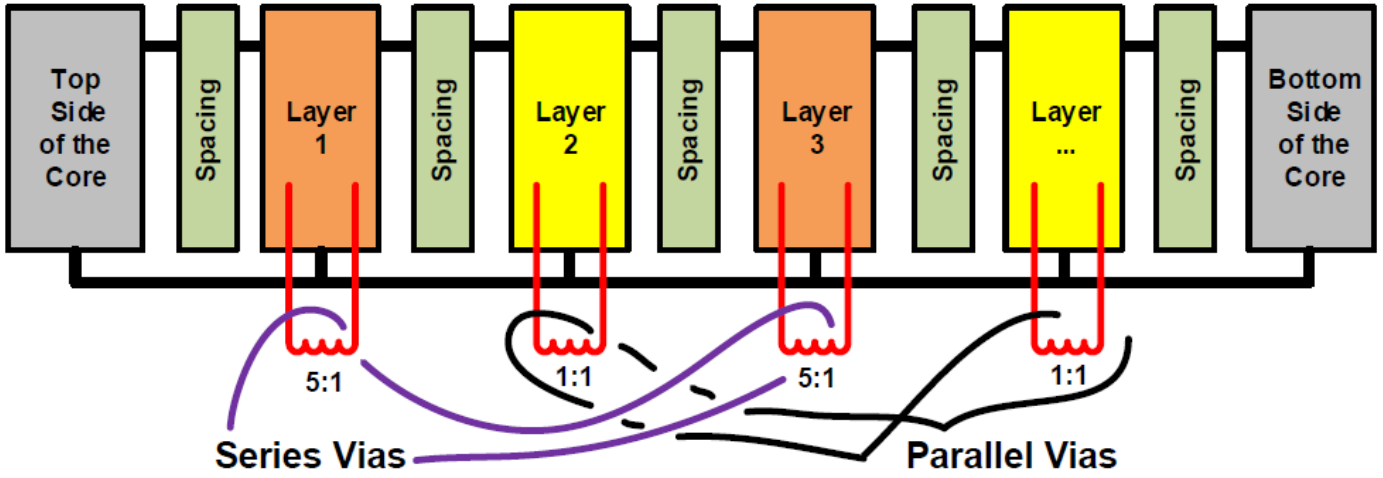
- 1-D energy wave (Poynting vector) propagation principles



- Modular lumped circuit models for repeating building blocks



Modeling a Single Conductor Layer

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Field diffusion equations:

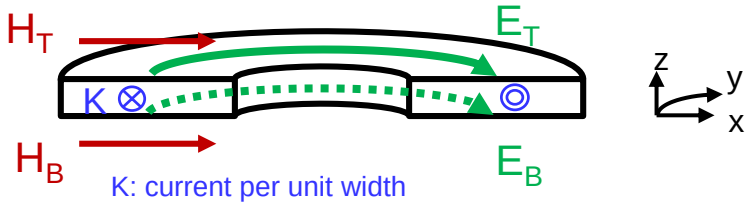
$$H_X(z) = \frac{H_T \sinh(\Psi z) + H_B \sinh(\Psi(h-z))}{\sinh(\Psi h)}$$

Ampere's law:

$$\nabla \times H = J = \sigma E$$

$$\Psi = \frac{1+j}{\delta} \qquad \delta = \sqrt{\frac{2}{\mu\omega\sigma}}$$

Electromagnetic Fields



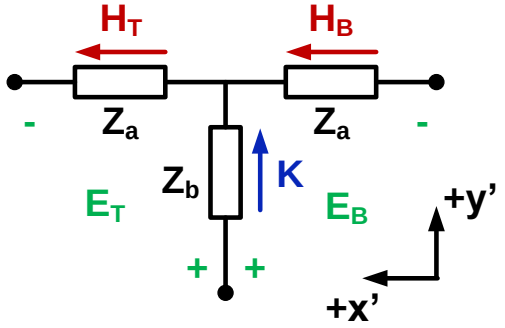
E field as a function of H and K:

$$\begin{cases} E_T = E_Y(h) = \dfrac{\Psi}{\sigma}\left(\dfrac{H_T e^{\Psi h} - H_B}{e^{\Psi h} - e^{-\Psi h}} - \dfrac{H_B - H_T e^{-\Psi h}}{e^{\Psi h} - e^{-\Psi h}}\right) \\ E_B = E_Y(0) = \dfrac{\Psi}{\sigma}\left(\dfrac{H_T - H_B e^{-\Psi h}}{e^{\Psi h} - e^{-\Psi h}} - \dfrac{H_B e^{\Psi h} - H_T}{e^{\Psi h} - e^{-\Psi h}}\right) \end{cases}$$

$$Z_a = \frac{\Psi(1 - e^{-\Psi h})}{\sigma(1 + e^{-\Psi h})}$$

$$Z_b = \frac{2\Psi e^{-\Psi h}}{\sigma(1 - e^{-2\Psi h})}$$

Modular Layer Model



KVL/KCL relationships:

$V/m \quad \Omega \quad A/m$

$$\begin{cases} E_T = Z_a H_T + Z_b K & \text{KVL} \\ E_B = Z_b K - Z_a H_B & \text{KVL} \\ K = H_T - H_B & \text{KCL} \end{cases}$$

***H* & *K*:** through variables ~ unit (**A/m**)
***E*:** across variable ~ unit (**V/m**)
***Z_a*, *Z_b*:** impedances ~ unit (**Ω**)

Modeling Two Adjacent Layers

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Intuition:

- *Two three-terminal networks*
- *Connected by the H field between them*

Faraday's Law and Field Continuity

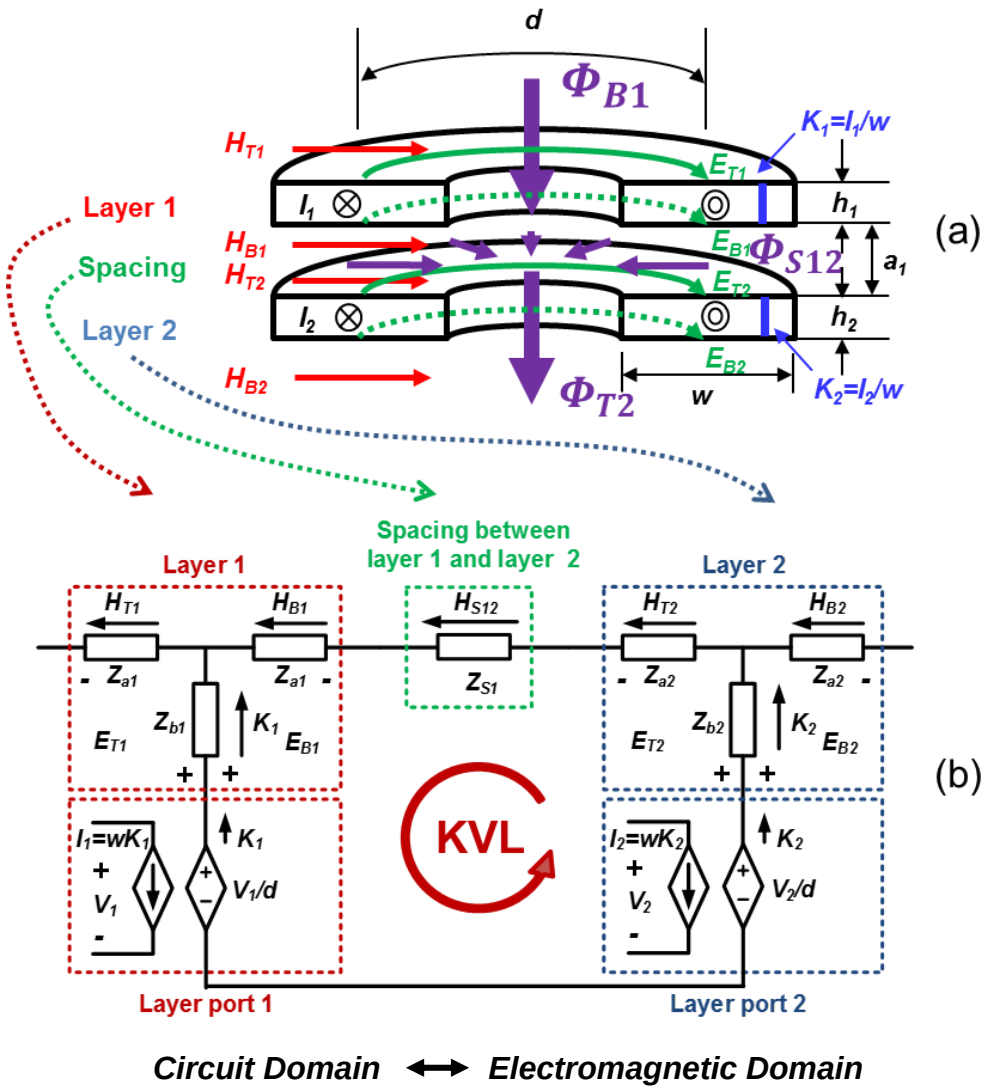
$$E_{B1}d - V_1 = -\frac{d\Phi_{B1}}{dt} \qquad E_{T2}d - V_2 = -\frac{d\Phi_{T2}}{dt}$$

$$\frac{d\Phi_{T2}}{dt} = \frac{d\Phi_{B1}}{dt} + \frac{d\Phi_A}{dt}$$

Flux Linking Two Layers:

An additional KVL equation

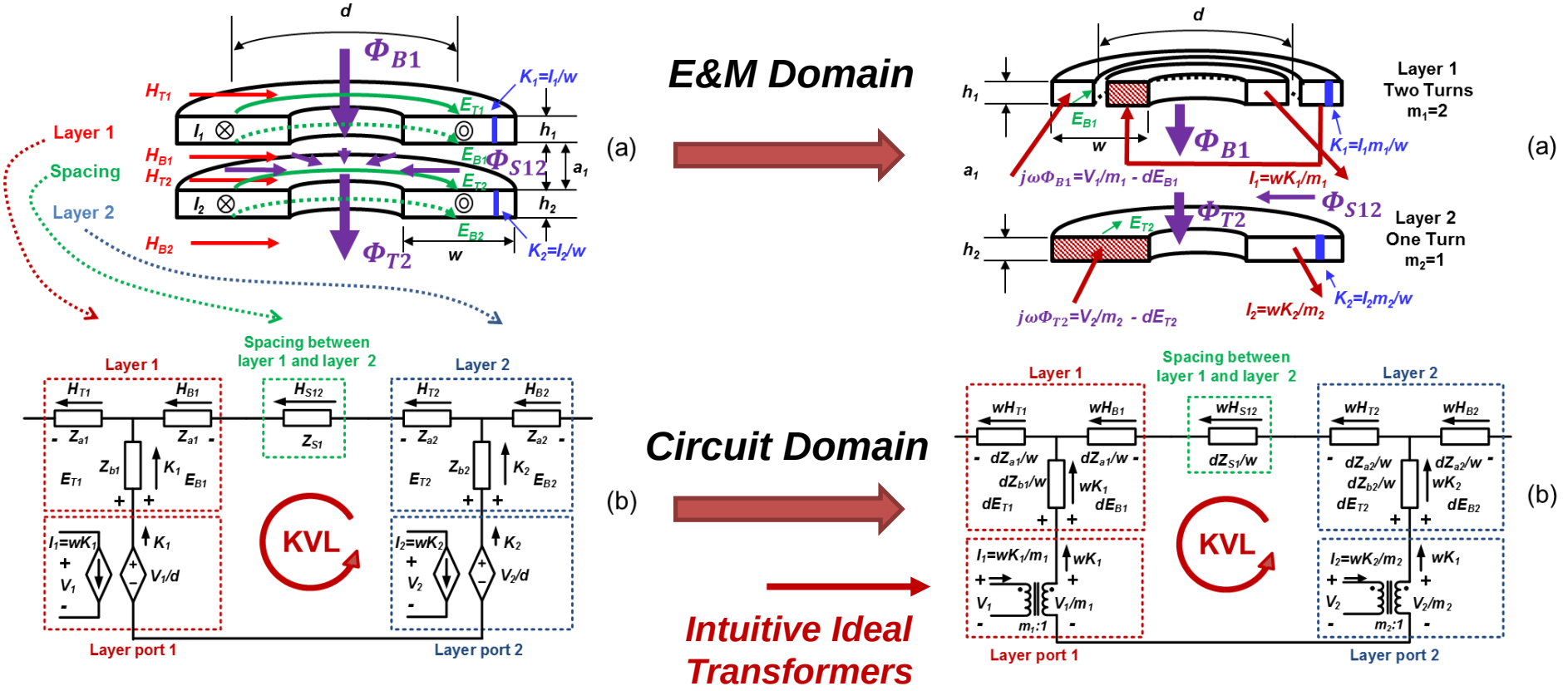
$$\underbrace{j\omega\mu_0 a_1}_{\Omega}\underbrace{H_{S12}}_{A/m} = \underbrace{\frac{V_2}{d} - E_{T2} - \frac{V_1}{d} + E_{B1}}_{V/m}$$



Modeling Layers with Multiple Turns

Fields distributions in multiple-turns layers are linearly related to those in single-turn layers

Multiple turns → Additional Linear Conversions

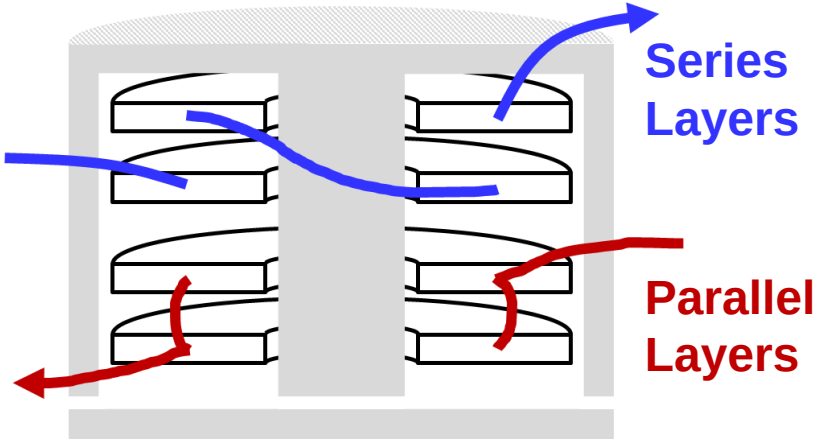


Modeling Electrical Interconnects (Vias)

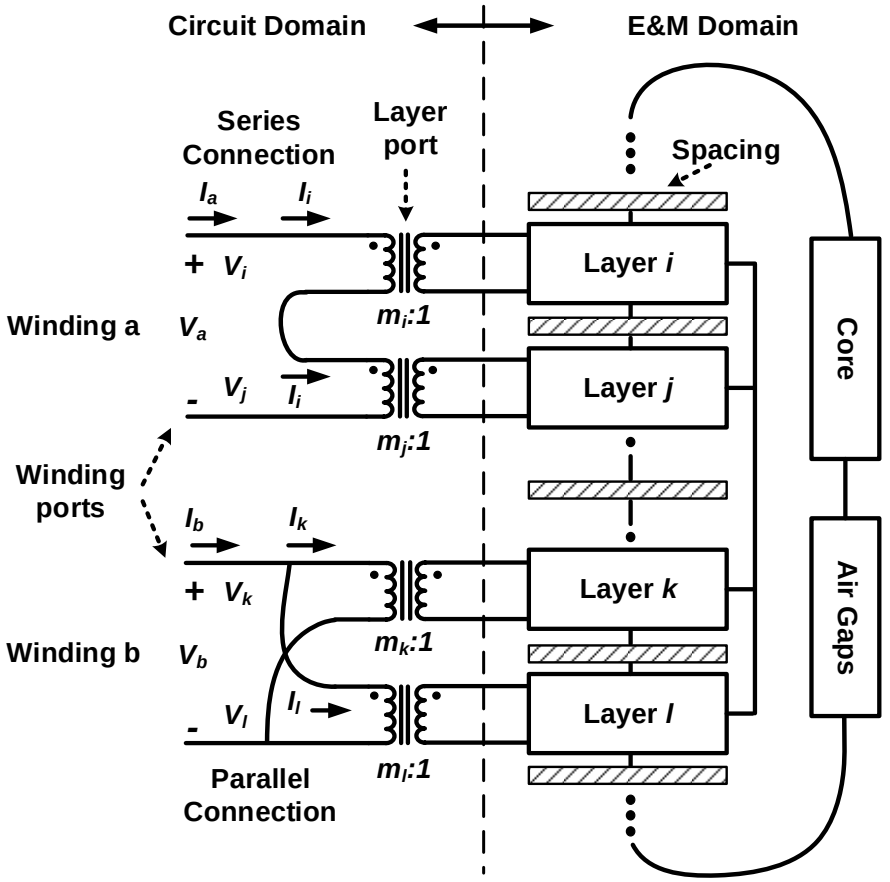
Modeling vias is equivalent to adding KVL, KCL constraints:

Layer i and Layer j in series
Layer k and Layer l in parallel

$$\begin{cases} V_i + V_j = V_a \\ V_k = V_l = V_b \end{cases} \qquad \begin{cases} I_i = I_j = I_a \\ I_k + I_l = I_b \end{cases}$$



Connect the layer ports in the same pattern as they are in the real circuit



An Open-Source SPICE Modeling Tool

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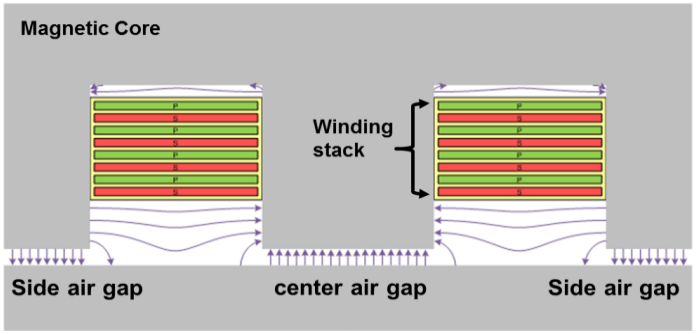
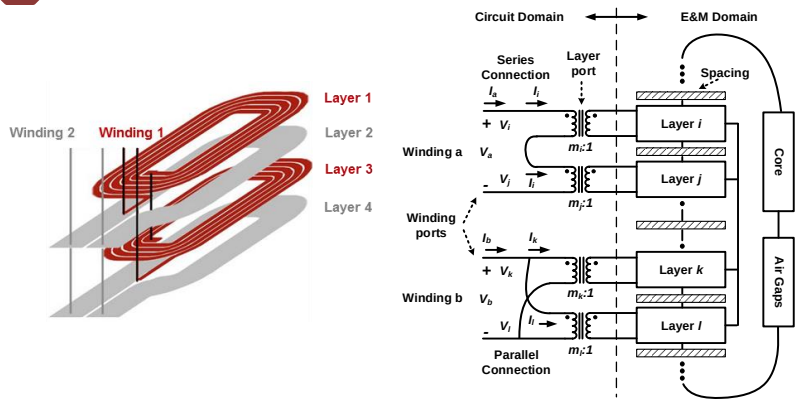
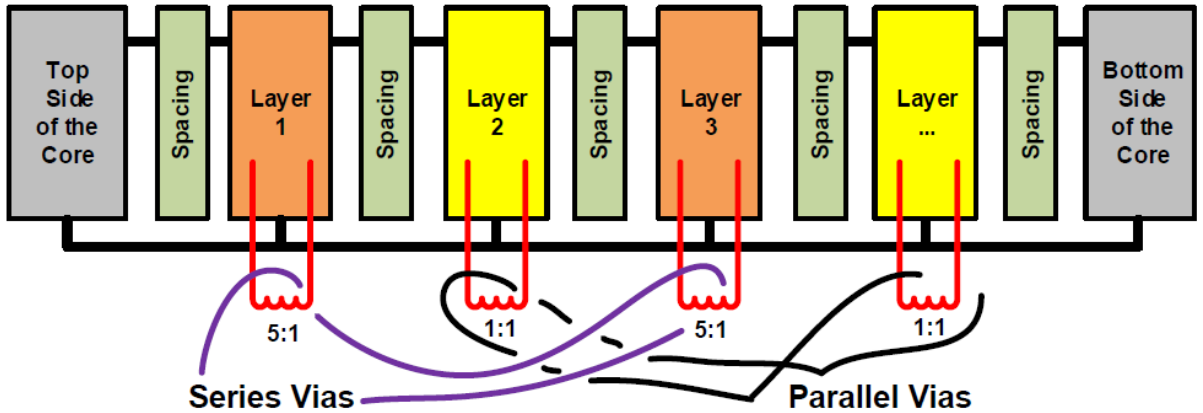
1 Geometry Information



3 SPICE Netlist



2 Modular Layer Model



Simulations!

GitHub

Search: M2SPICE

Impacts of Interleaving Patterns

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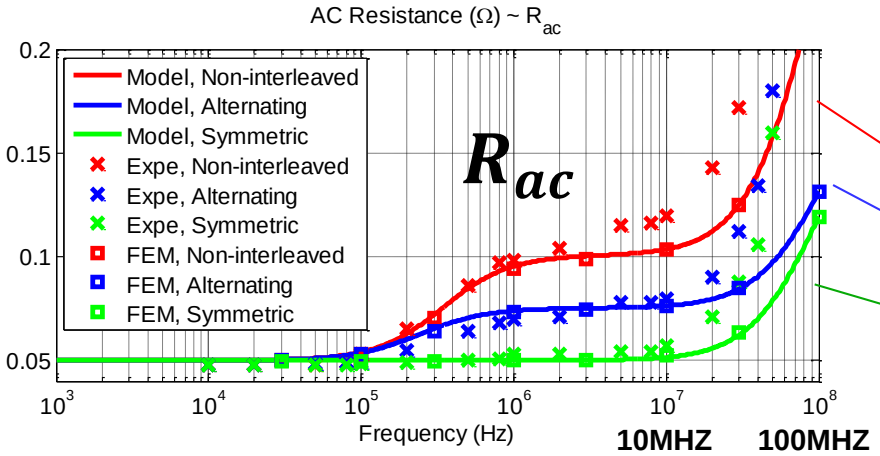
Comparing the P_{ac} and E_{ac} of three 1:1 transformers with three different interleaving patterns

Non interleaved

Alternating

Symmetric

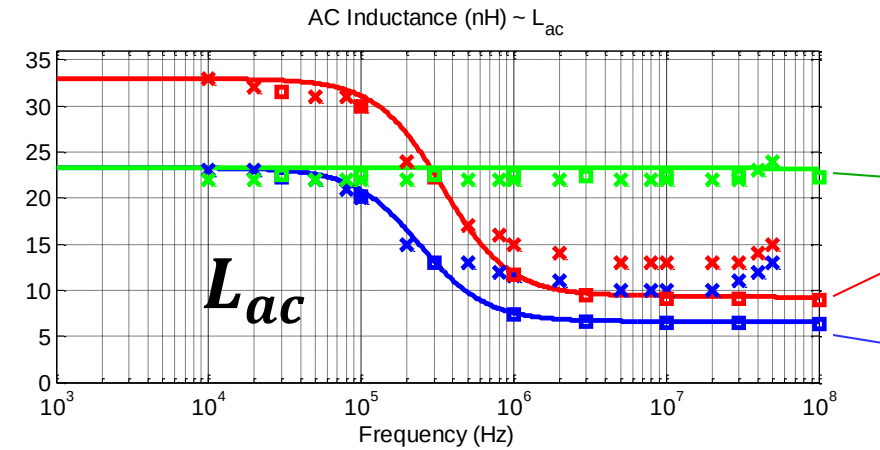


$$P_{ac} = \sum I^2 R_{ac}$$

Non Interleaved

Alternating

Symmetric



$$E_{ac} = \frac{1}{2}\sum I^2 L_{ac}$$

Symmetric

Non interleaved

Alternating

Interleaving has to be done in the right way !!!

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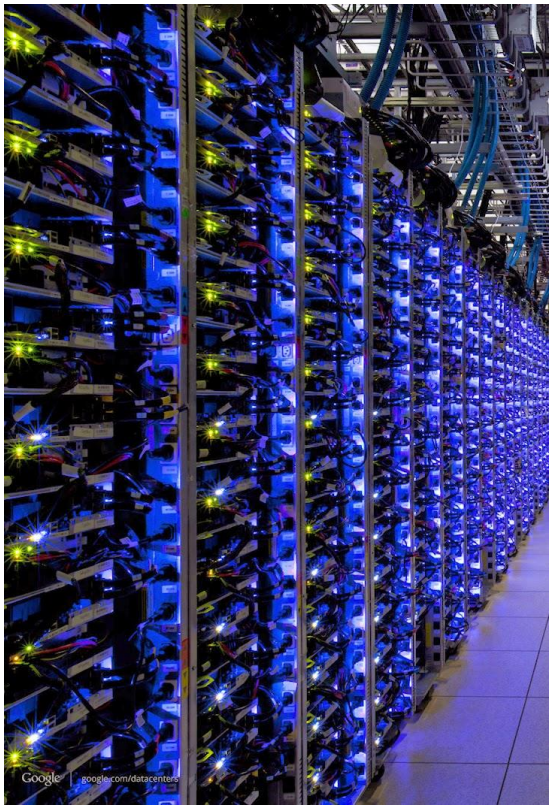
Multi-Input Multi-Output Power Electronics Systems

Battery Banks



Server Racks

Solar Farms

Power Management for Storage Servers

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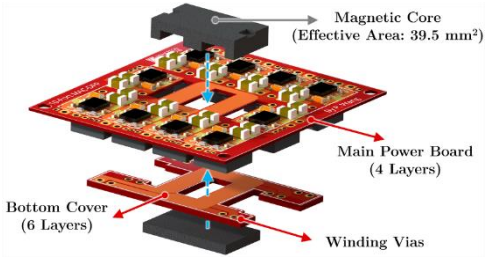
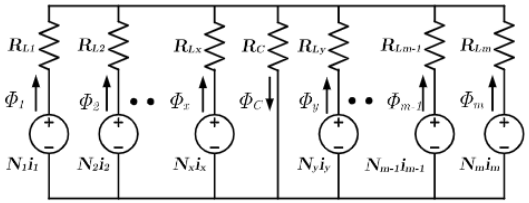
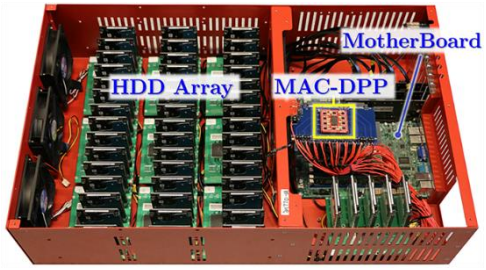
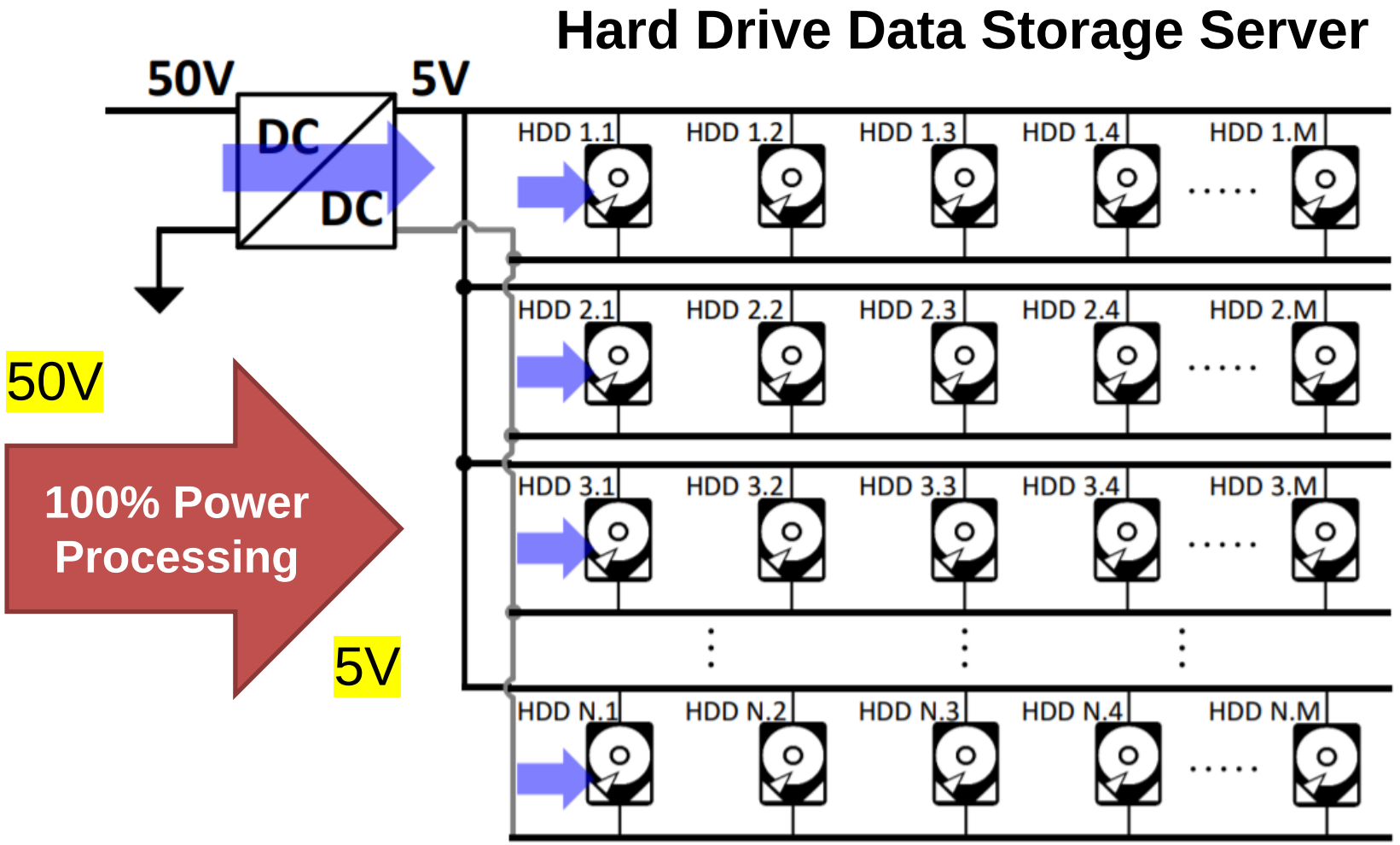
Magnetics Design → **Circuit Topology** → **System Integration**



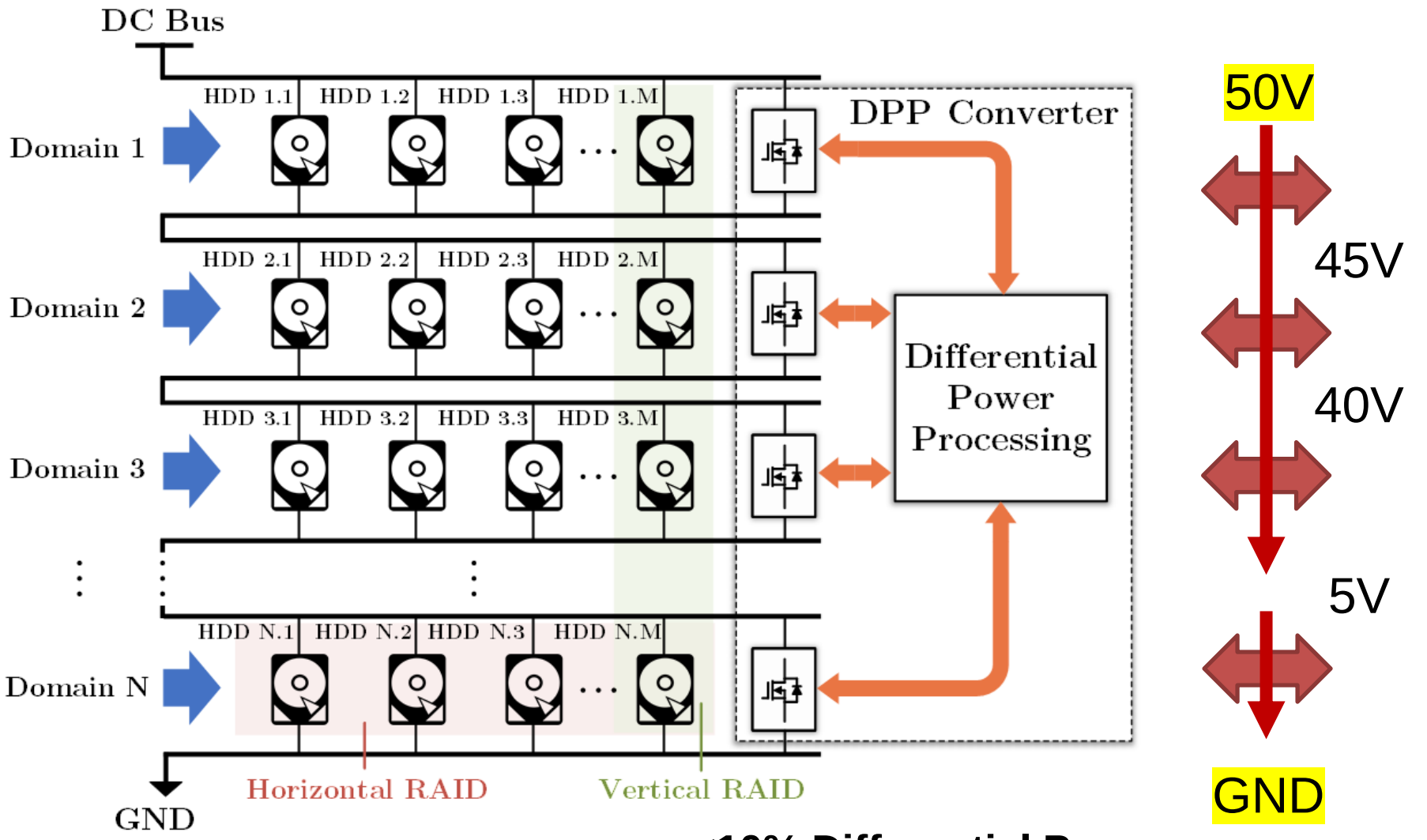




A Conventional Dc-Dc Approach



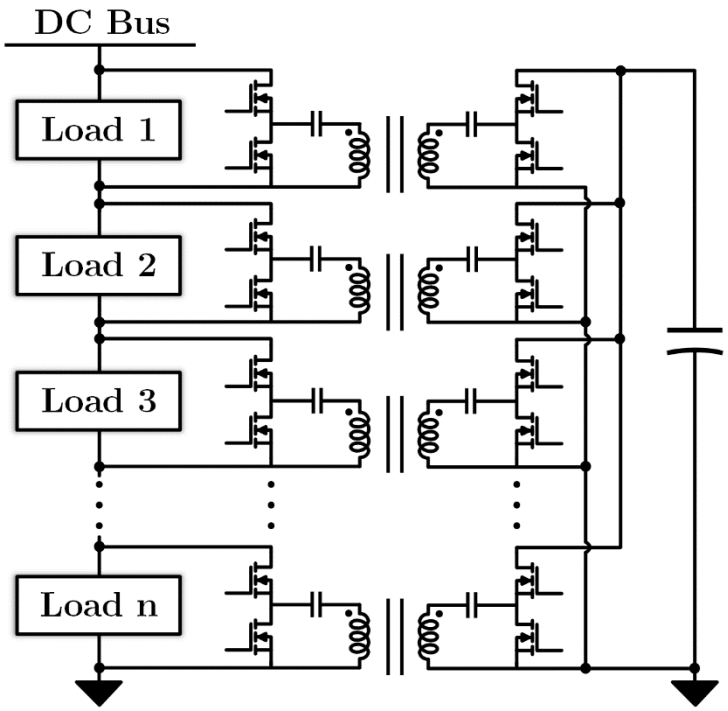
Differential Power Processing



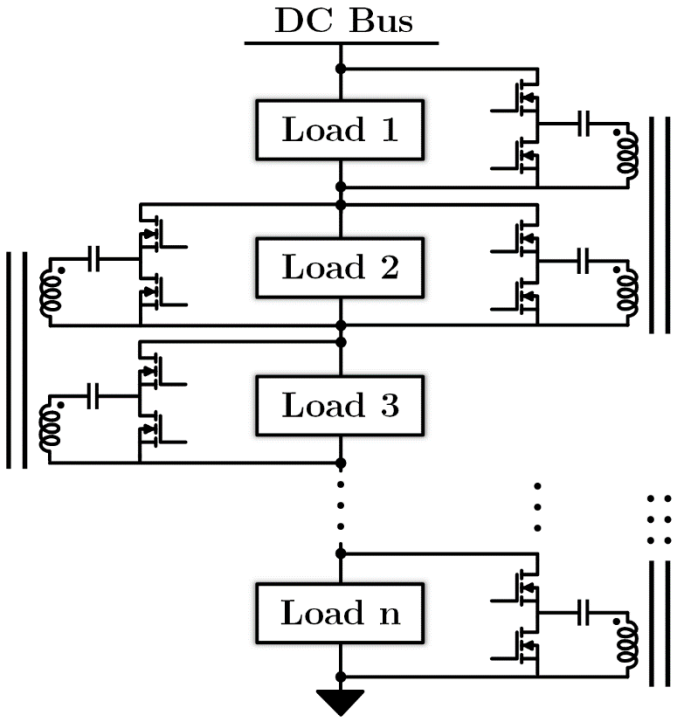
<10% Differential Power

Existing DPP Solutions

DPP with a buffer port

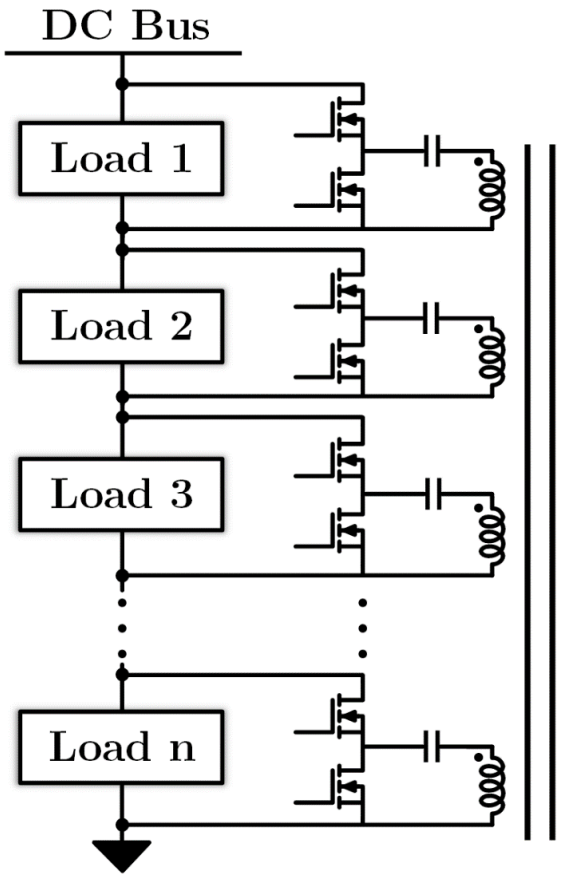


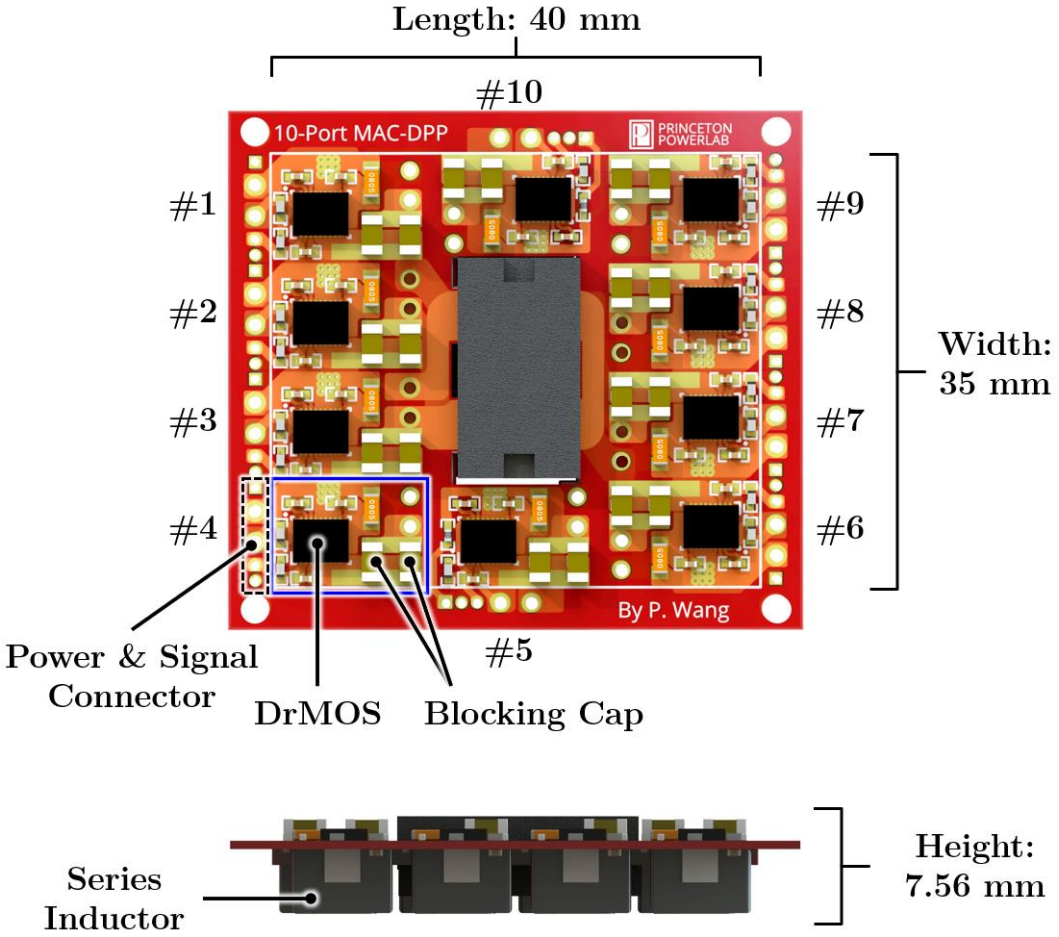
Ladder DPP



- E. Candan, P. S. Shenoy and R. C. N. Pilawa-Podgurski, “A Series-Stacked Power Delivery Architecture with Isolated DifferentialPower Conversion for Data Centers,” TPEL 2016.
- H. Schmidt and C. Siedle, “The charge equalizer-a new system to extend battery lifetime in photovoltaic systems, UPS and electricvehicles,” INTELEC 1993.

Fully-Coupled DPP Architecture





- P. Wang, M. Chen et al., "A 99.7% Efficient 300 W Hard Disk Drive Storage Server with Multiport Ac-Coupled Differential Power Processing (MAC-DPP) Architecture," ECCE 2019

Multiwinding Transformer Design

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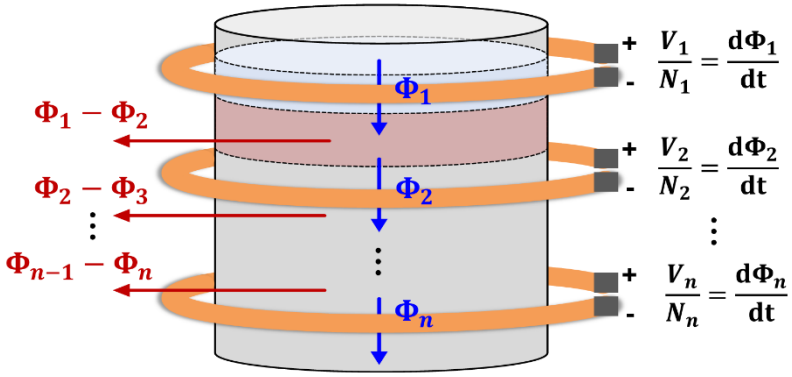
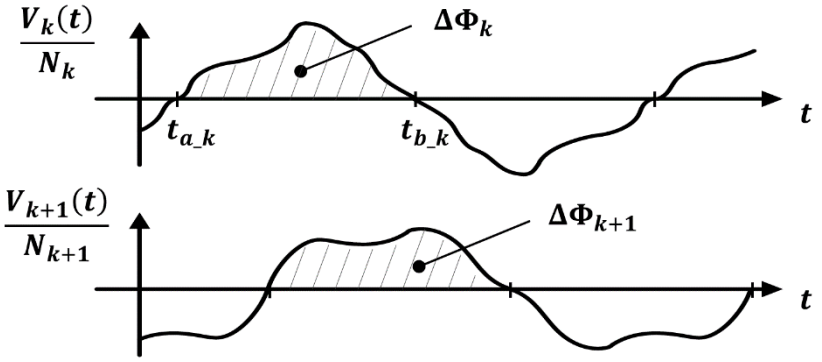
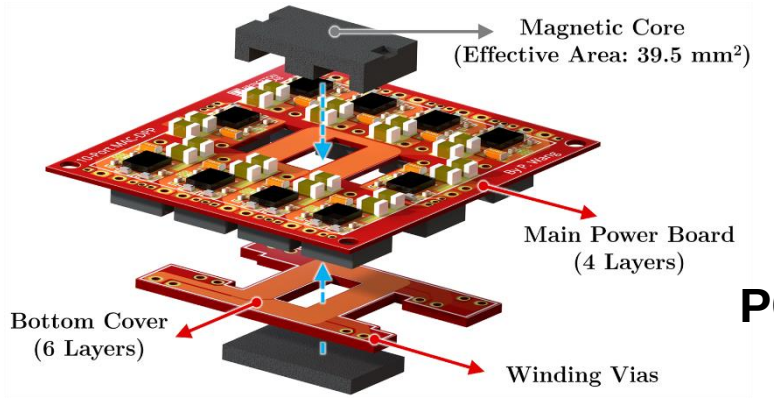
Transformer saturation requirements: maximum volt-seconds per turn



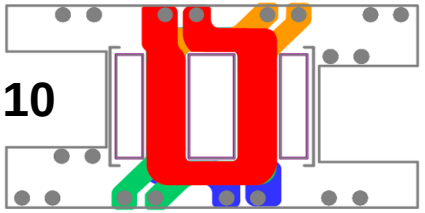


3D stacked multiwinding transformer with modular planar modeling

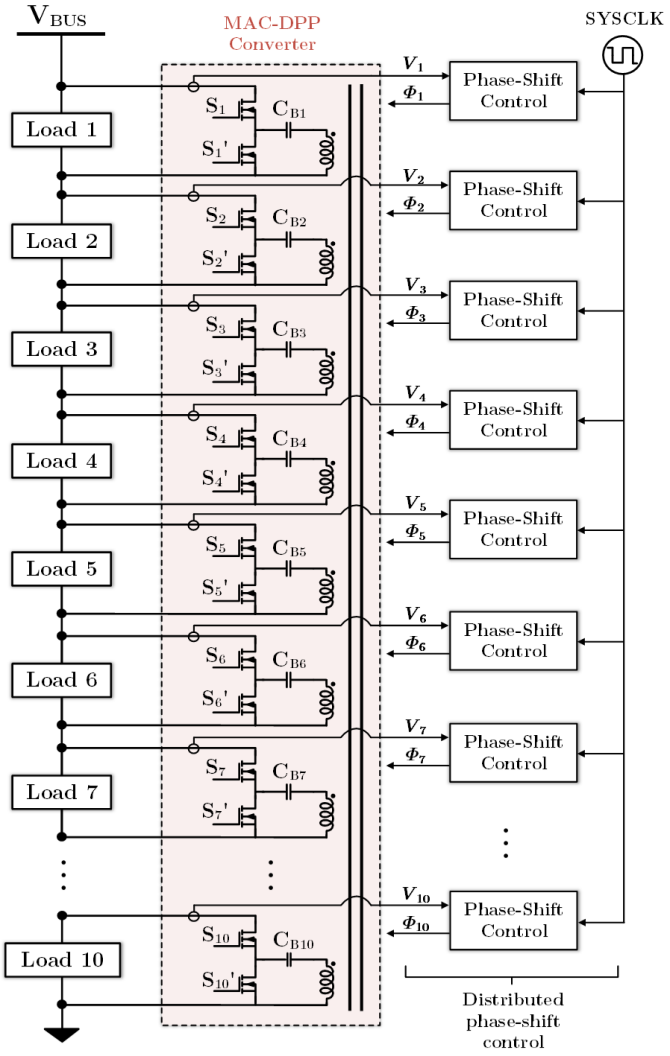


PCB1: Layer 1 – Layer 6

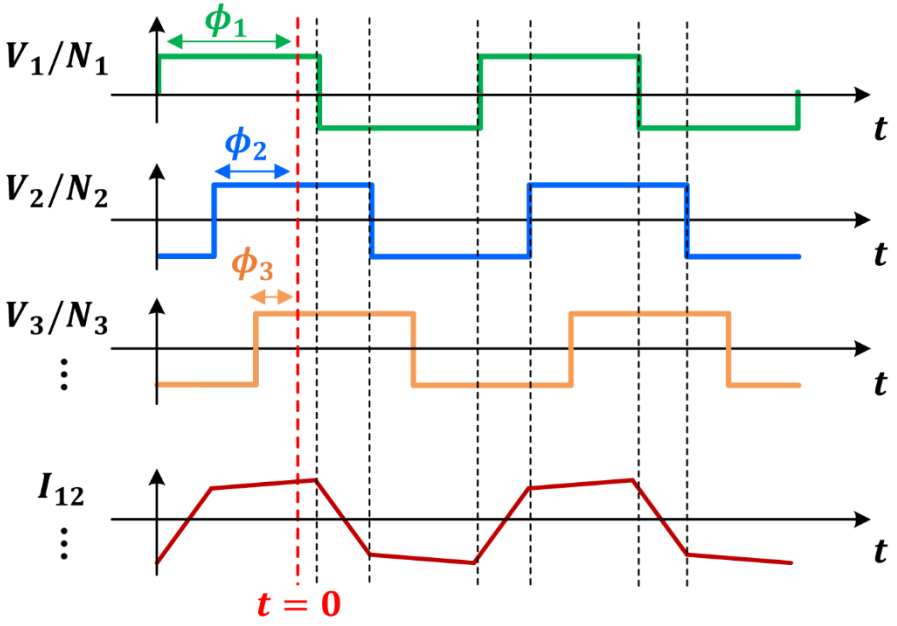
PCB2: Layer 7 – Layer 10



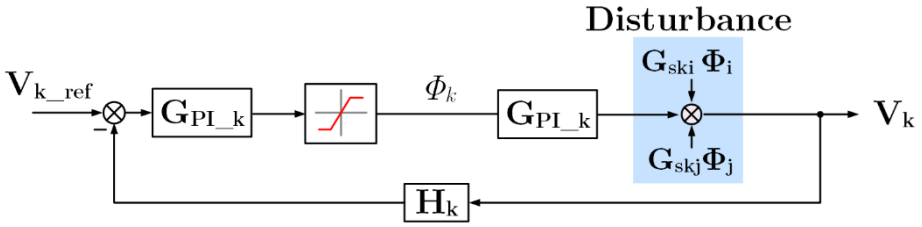
Distributed Phase Shift Control



Phase shift determines the power flow



Block diagram of the distributed control



Complete HDD Storage System

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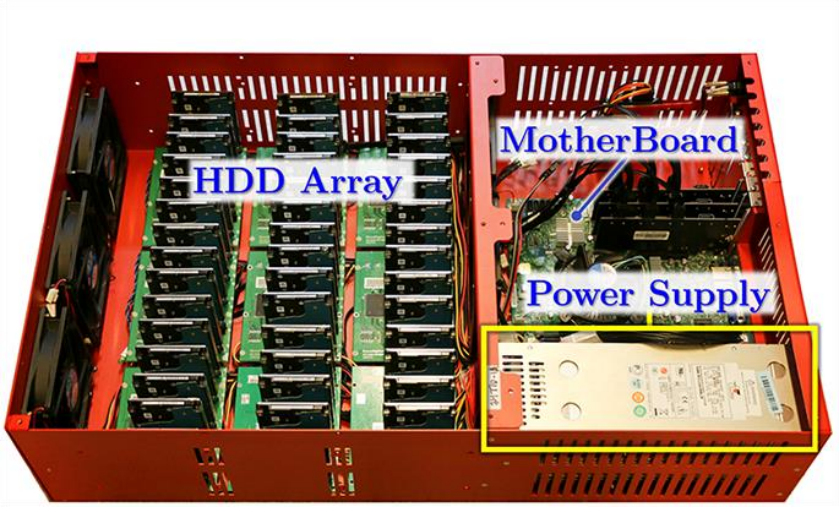
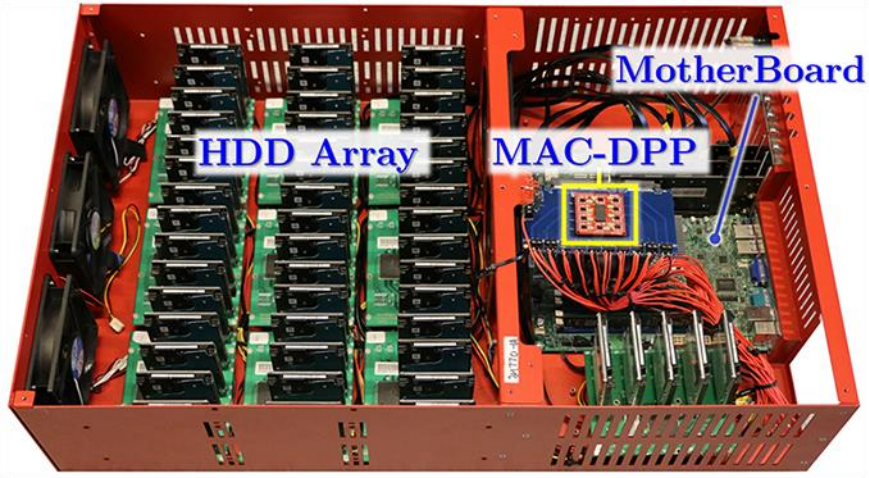
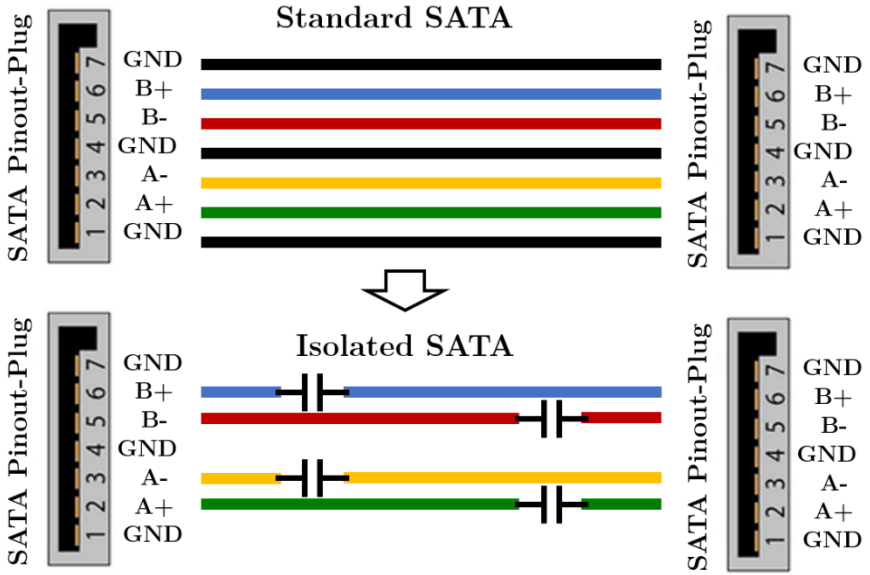
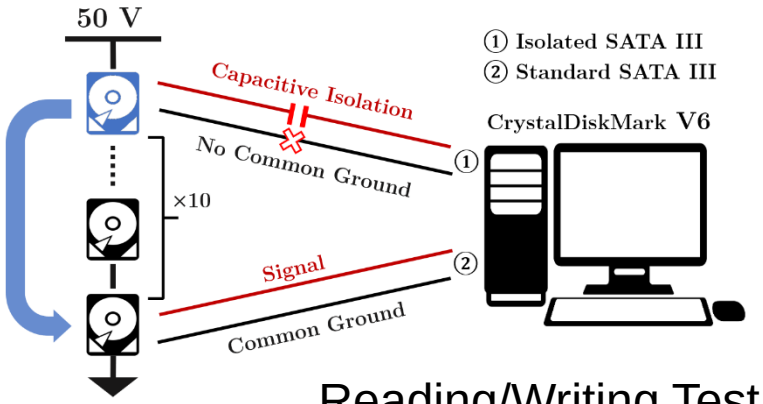


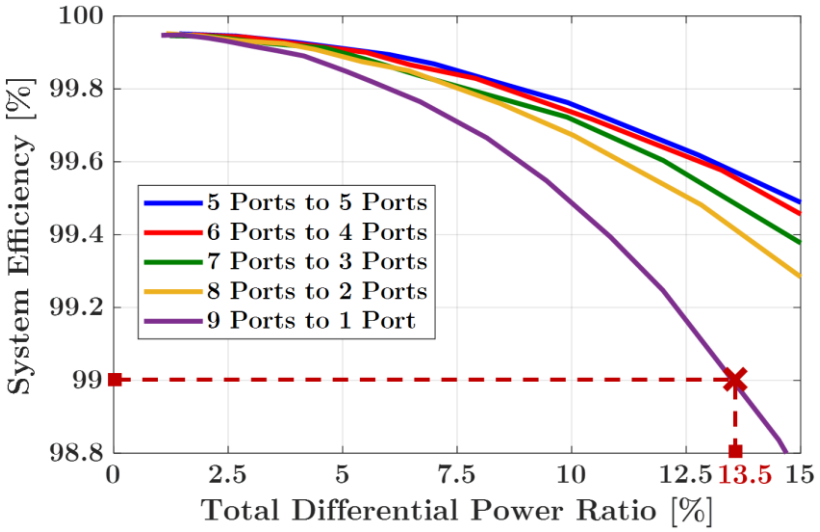


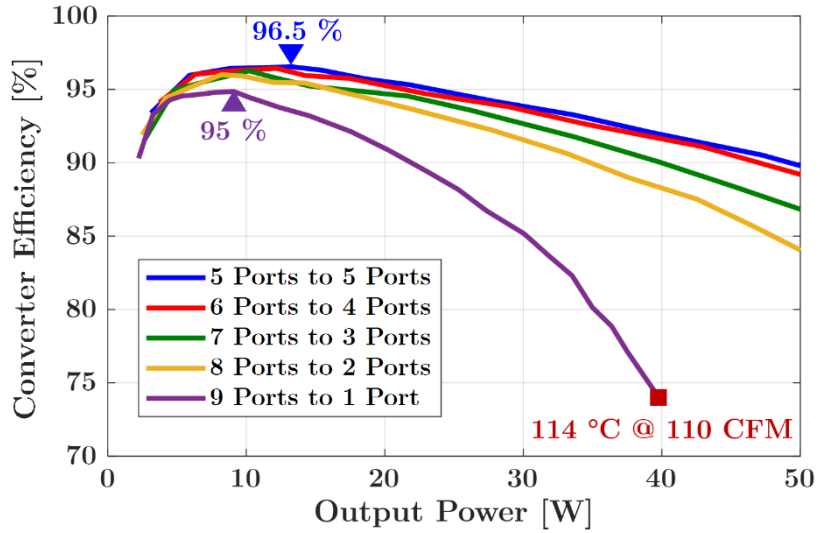


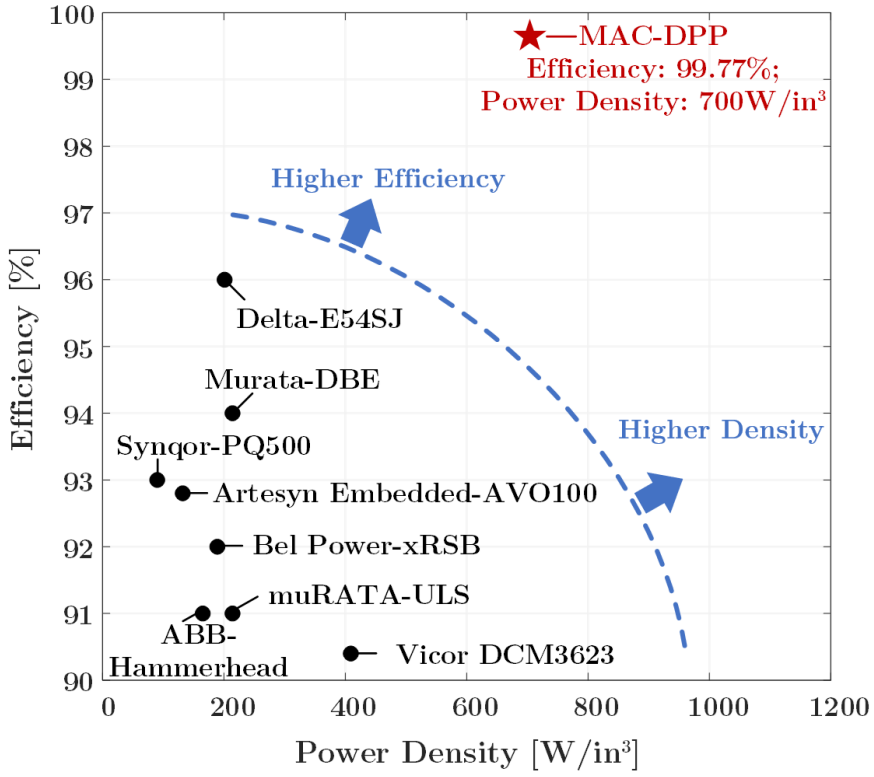


Reading/Writing Test

Performance of the DPP Architecture



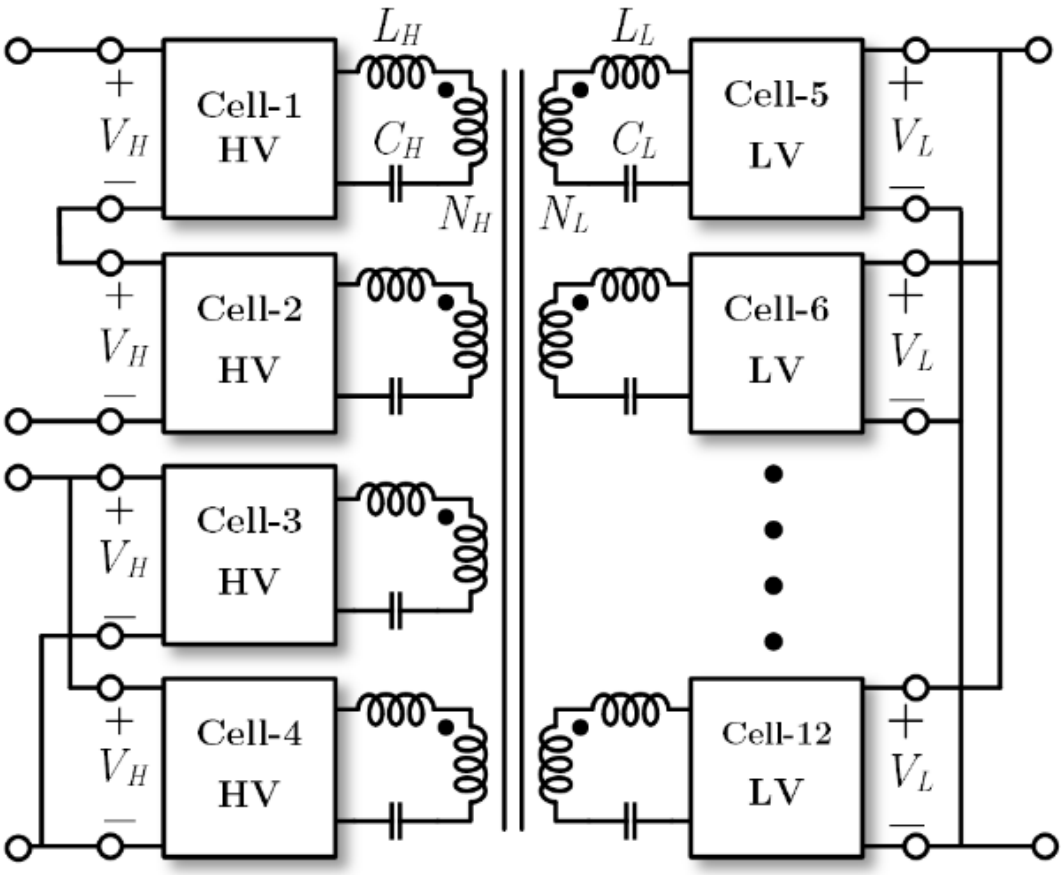




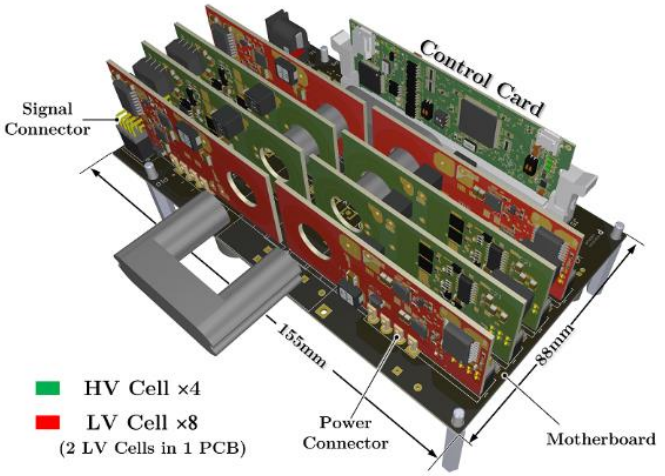
Summary:

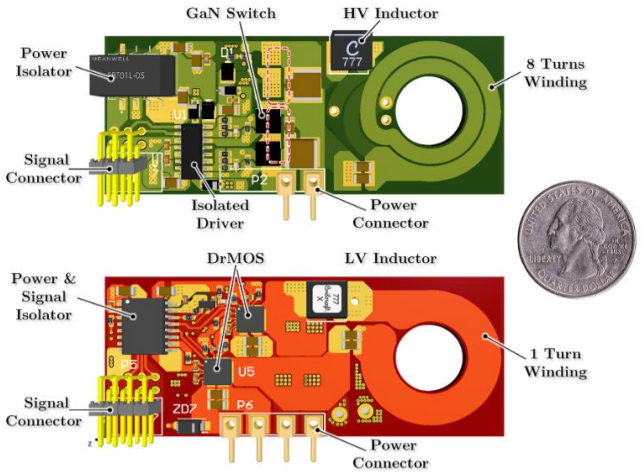
- Multiwinding transformer enables ultra high performance DPP
- DPP architecture fits well to large scale modular systems

MIMO Reconfigurable Energy Router



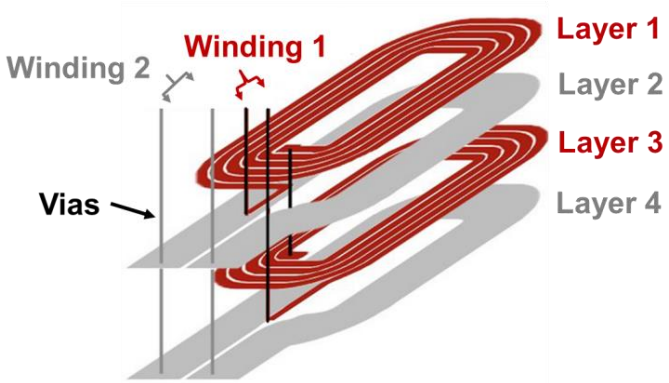
Series-Parallel Reconfigurable



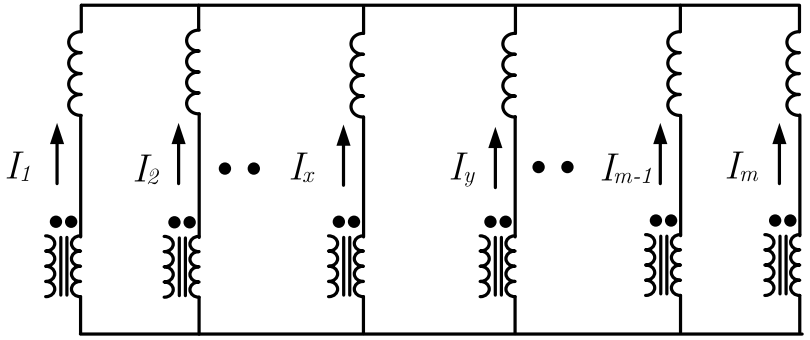


- Y. Chen, M. Chen et al., “LEGO-MIMO Architecture: A Universal Multi-Input Multi-Output (MIMO) Power Converter with Linear Extendable Group Operated (LEGO) Power Bricks,” ECCE19.

- Multiple winding coupled to a single flux linkage

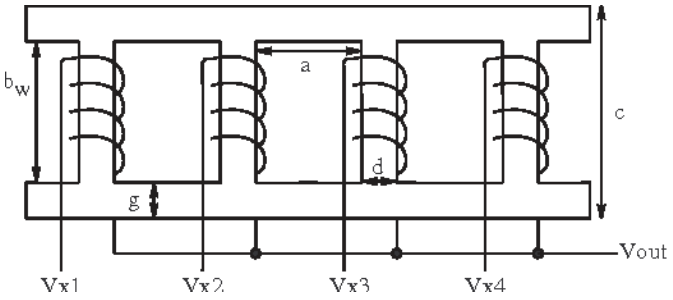


electrical circuit model

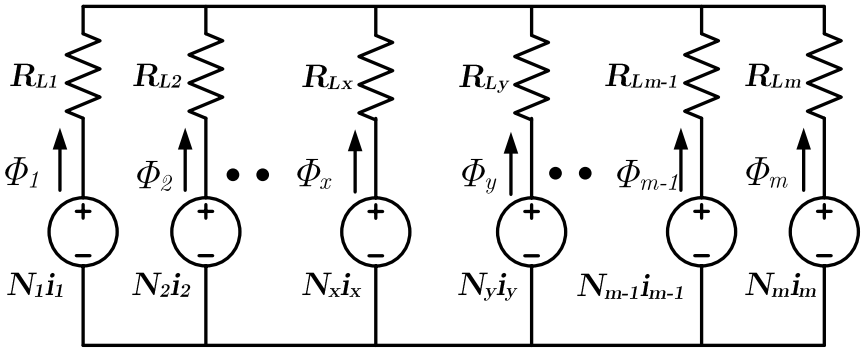


Inverse

- Multiple windings coupled to multiple flux linkages



reluctance circuit model



Circuit Models for Coupled Magnetics

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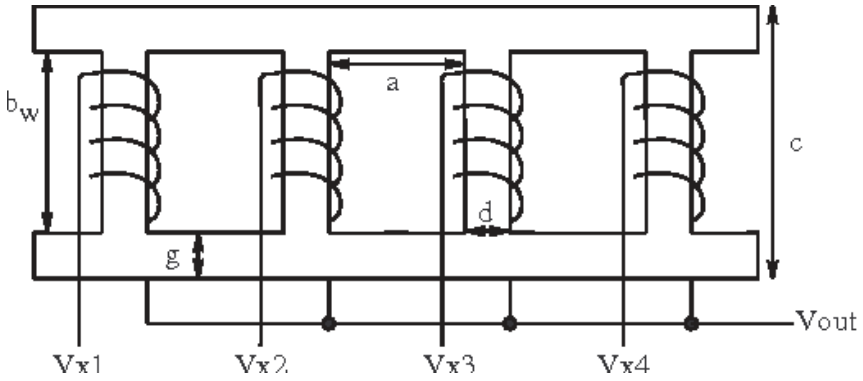
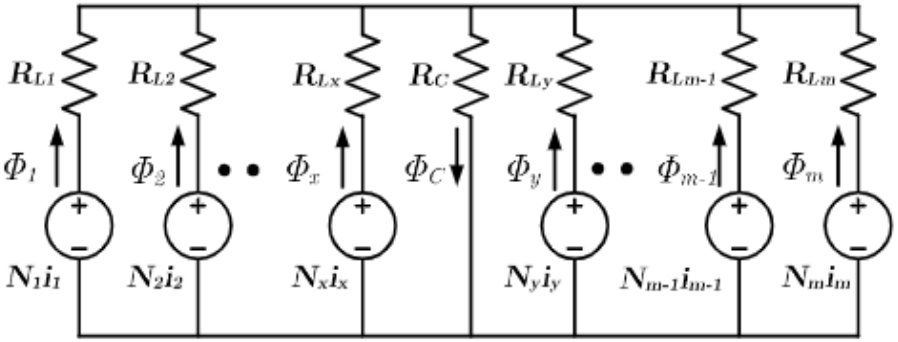
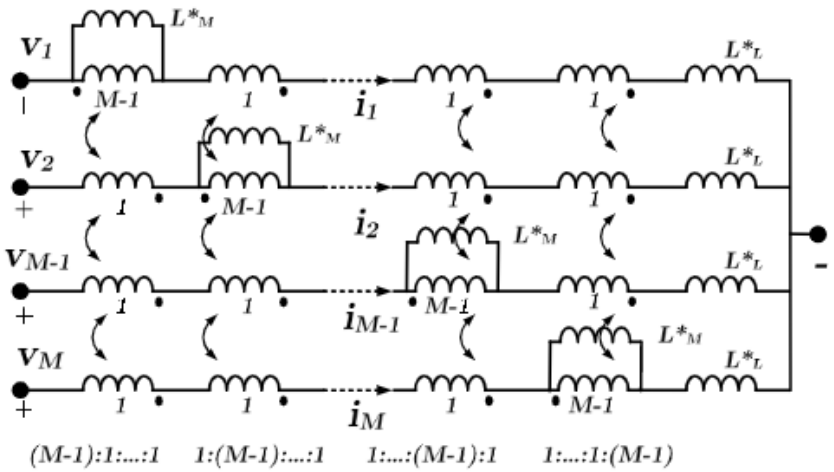
Physical Structure



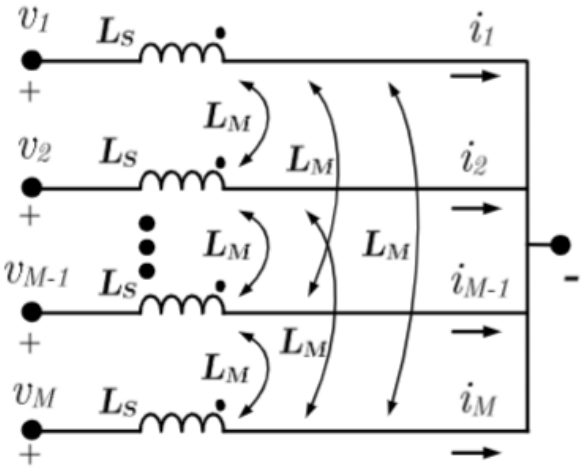
Reluctance Model



Multiwinding Transformer Model

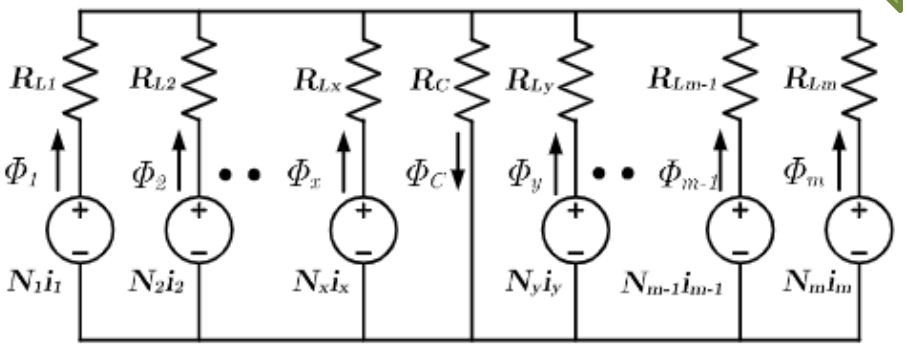


Inductance Matrix Model



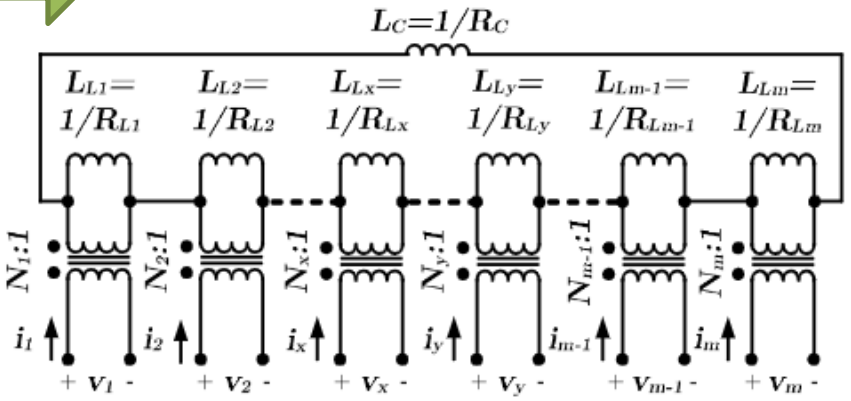
Permeance Model & Reluctance Model

Reluctance Model



dual

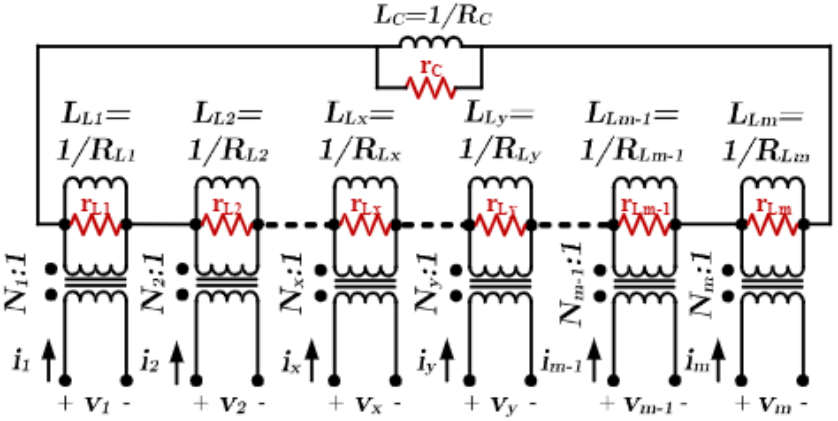
Permeance Model



Advantage of the Permeance Model

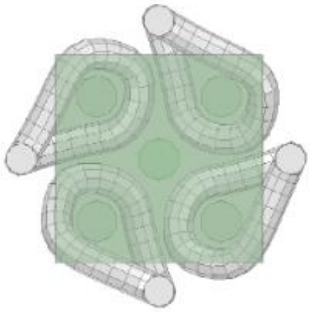
- Simple
- Intuitive
- No coupled inductors
- Explicit design equations
- Capability of capturing core loss

Permeance Model with Core Loss

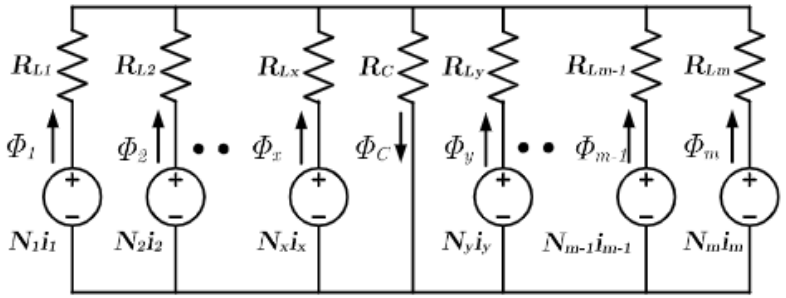


- D. Zhou and M. Chen, “Permeance Model for Multiphase Coupled Inductor, COMPEL 2020, submitted.

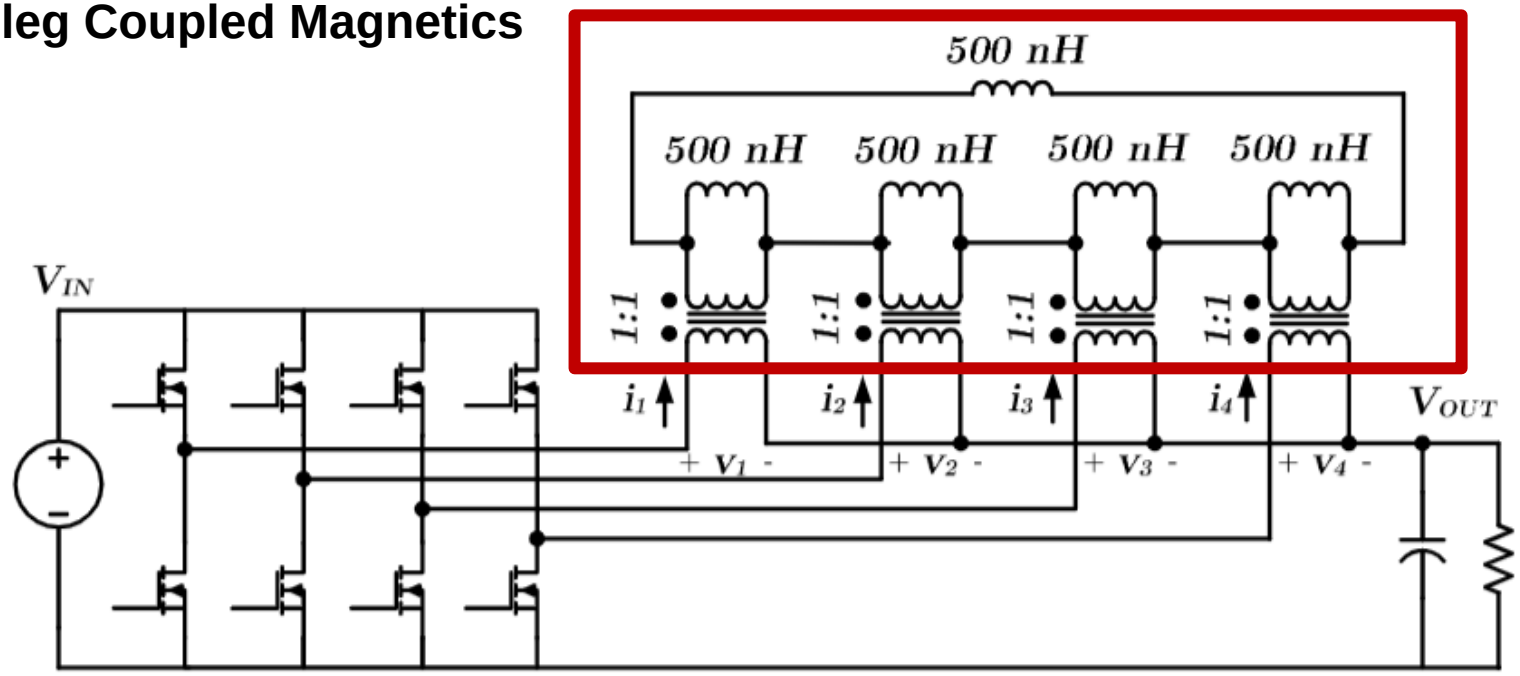
Permeance Model for SPICE Simulation



Multileg Coupled Magnetics

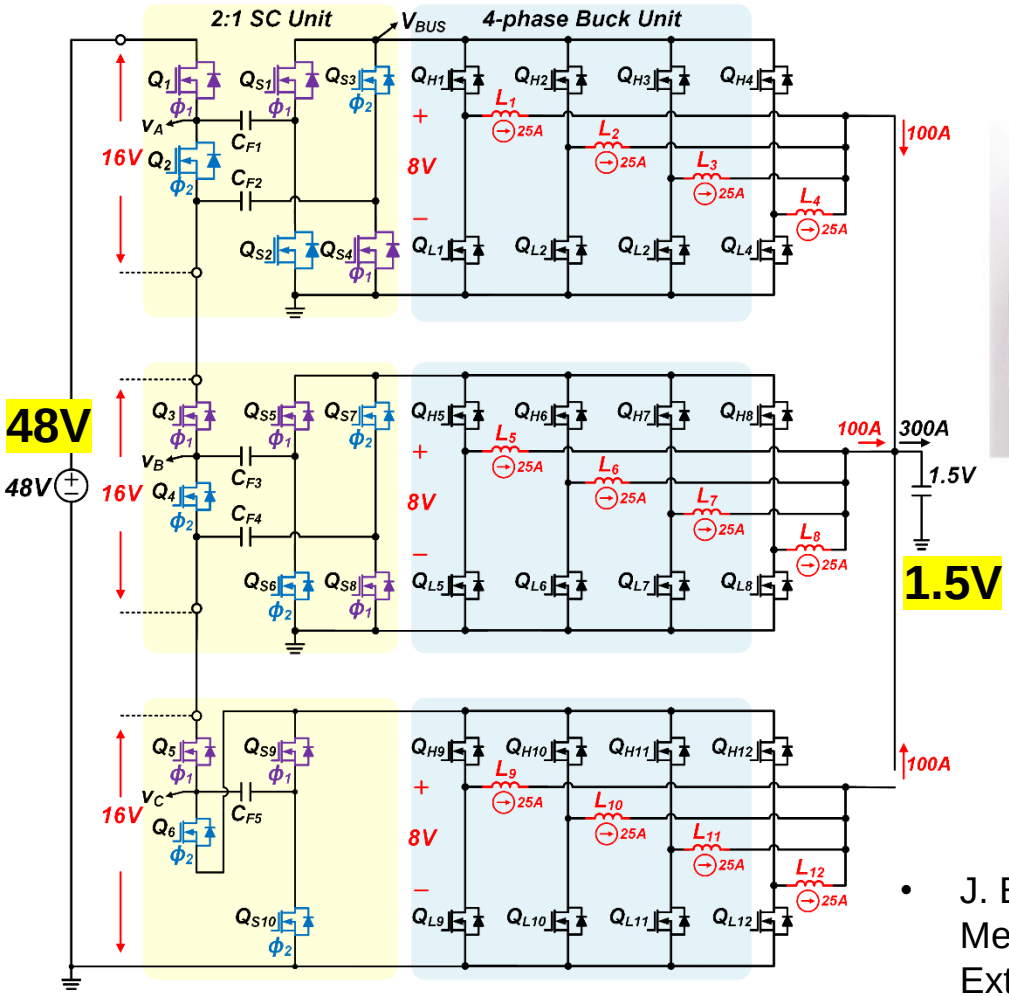


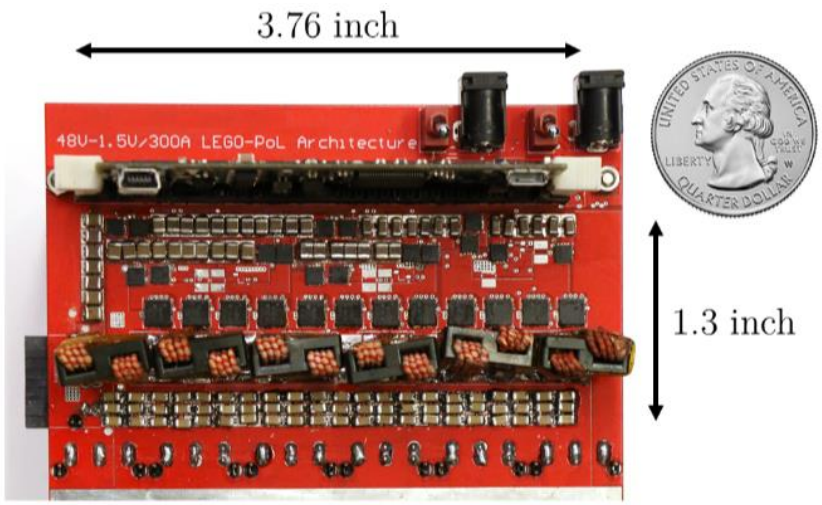
Topological duality

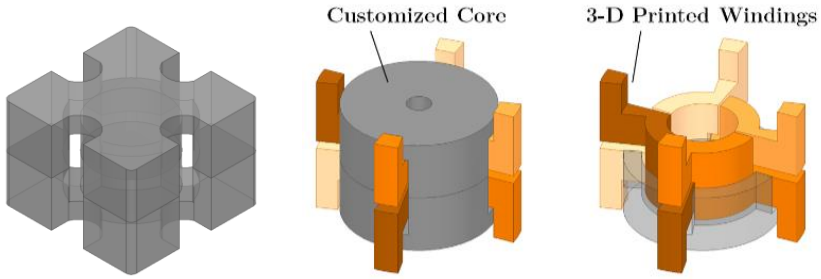


D. Zhou et al., “Permeance Model for Programmable Multiphase Coupled Magnetics”, COMPEL20, submitted

Hybrid Converter with Coupled Magnetics







- J. Baek, et al., "LEGO-PoL: A 93.1% 54V-1.5V 300A MergedTwo-Stage Hybrid Converter with a Linear Extendable Group Operated Point-of-Load (LEGO-PoL) Architecture," COMPEL 2019.

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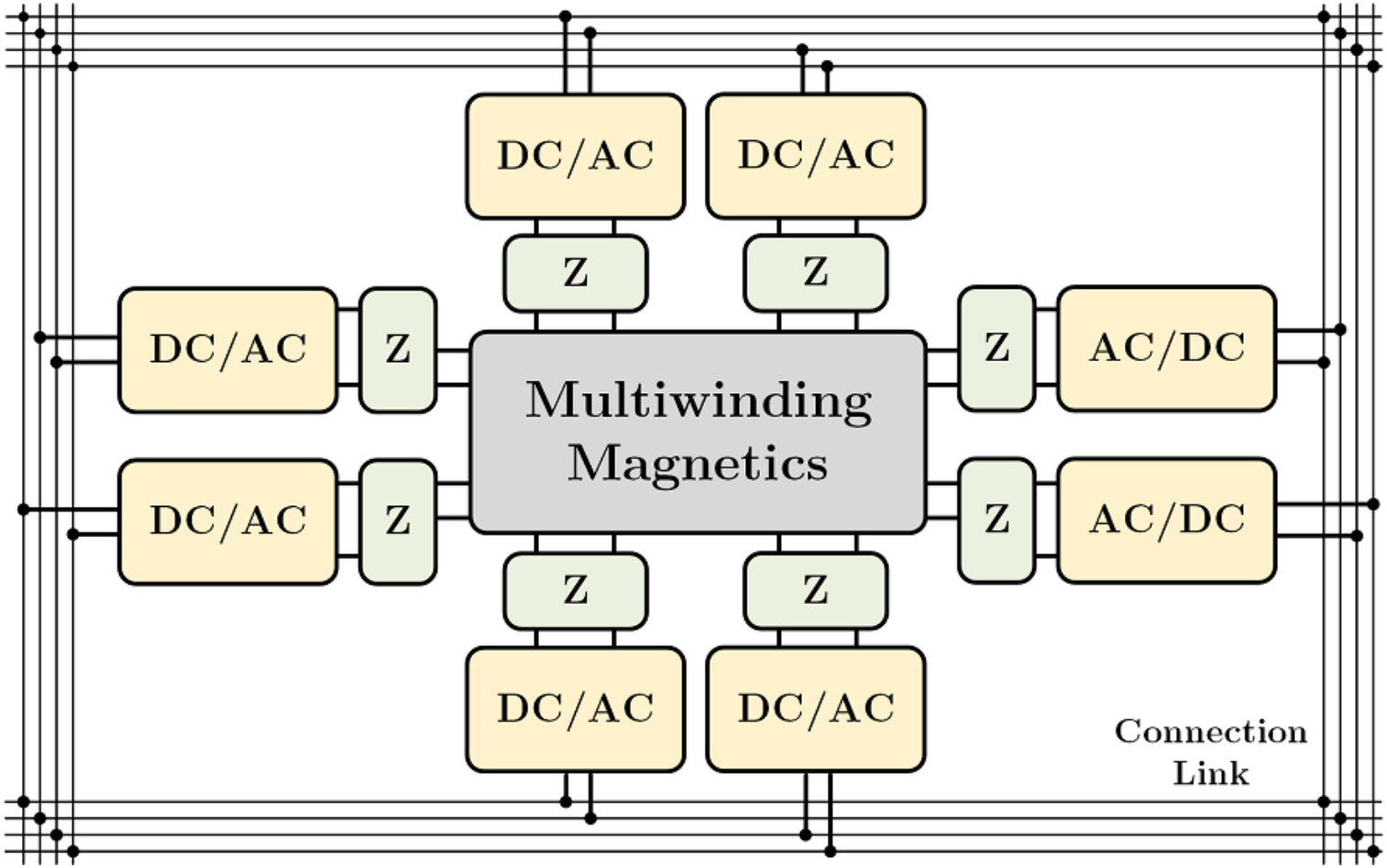
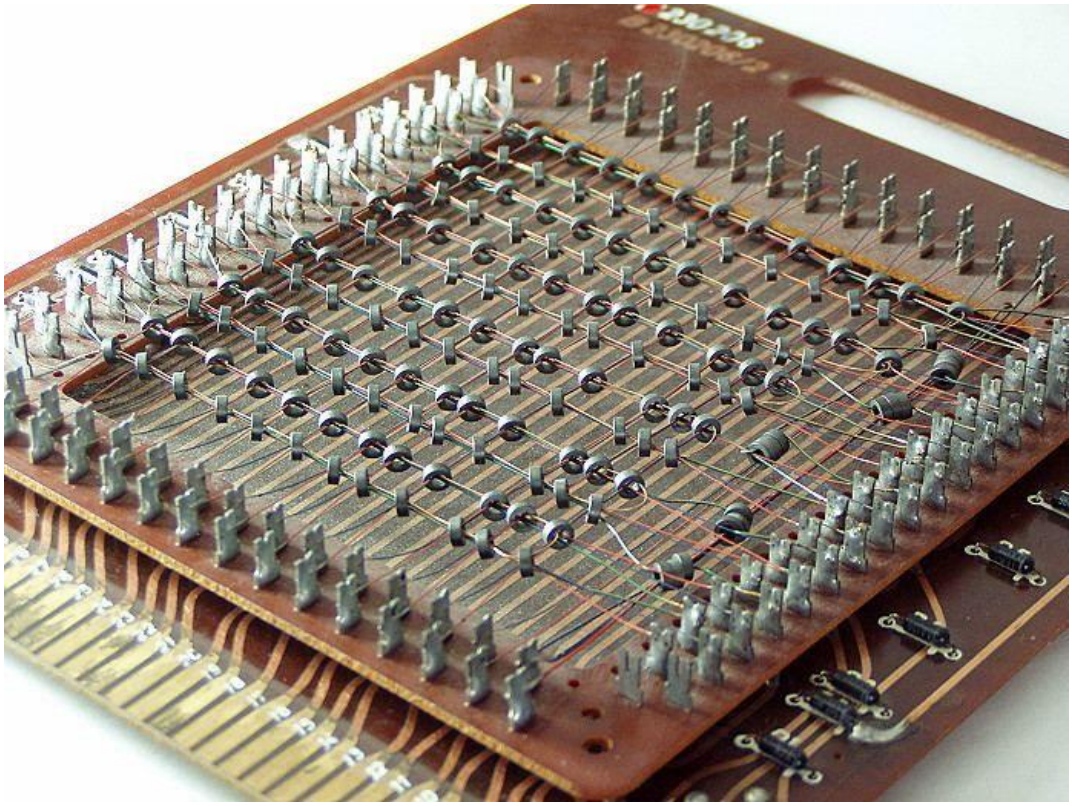
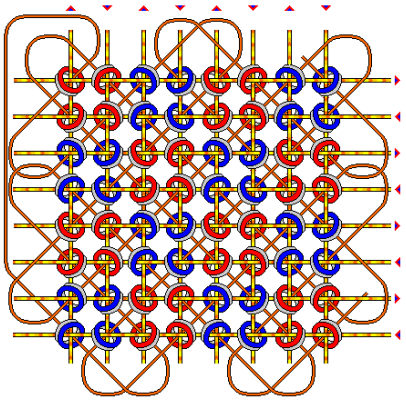
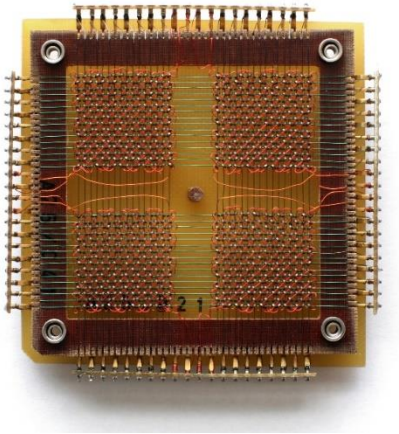
Towards a MIMO Magnetic Energy Processor



A Magnetic Memory in 1960s







- A 32 x 32 core memory storing 1024 bits of data
- Instead of processing information, we process energy

Summary

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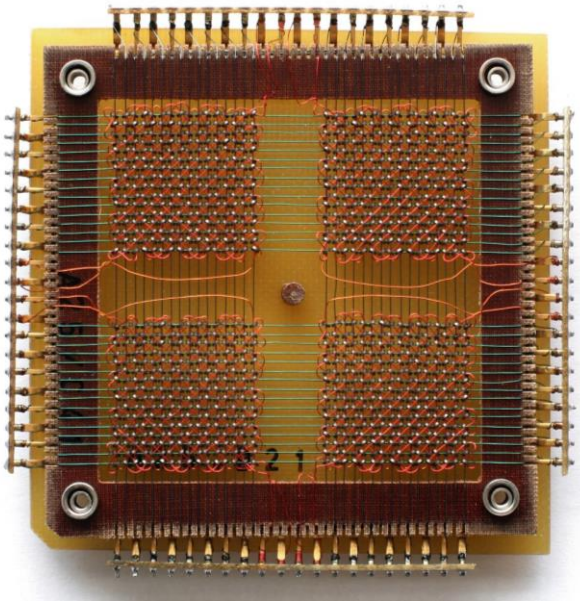
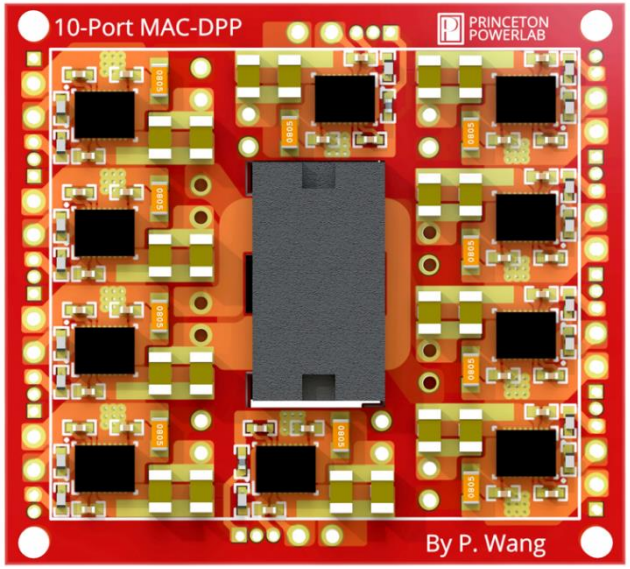
- **Exciting Opportunities for Power Electronics & Magnetics**

Information Processing



10101
01010
10101

Energy Processing



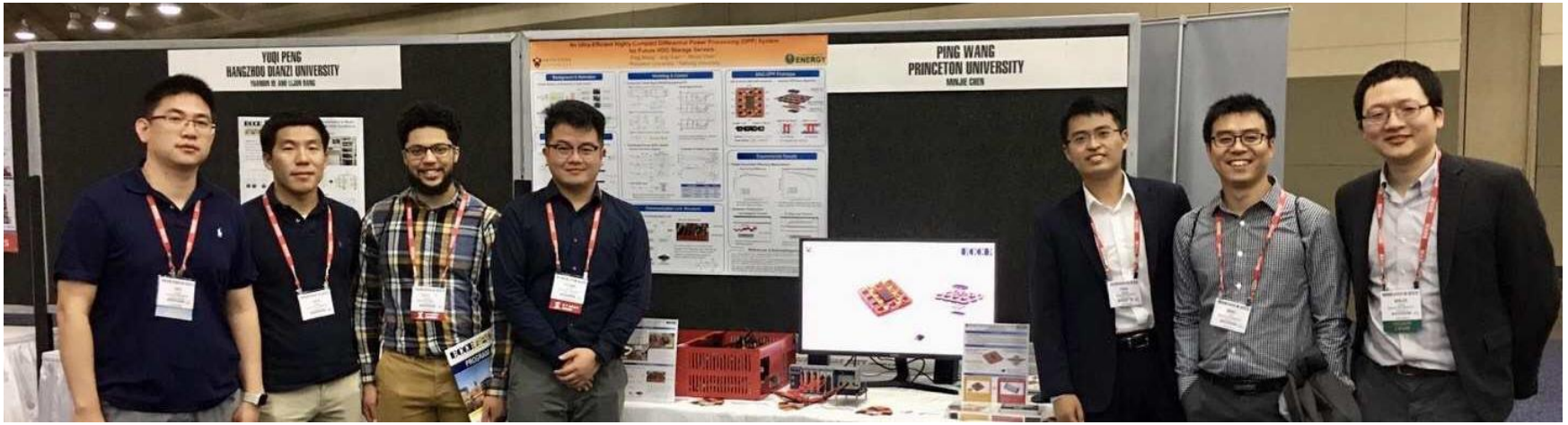
32 x 32 Magnetic Memory

10-Port MIMO Power Converter

More topologies and designs to be investigated!

Acknowledgements

Princeton Power Electronics Research Group



Research Sponsors and Collaborators

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- D.S. Gardner et al., “Review of on-chip inductor structures with magnetic films”, IEEE Trans. Magn., 2009
- M. Chen, “A Systematic Approach to Modeling Impedances and Current Distribution in Planar Magnetics,” TPEL16
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- E. Candan, P. S. Shenoy and R. C. N. Pilawa-Podgurski, “A Series-Stacked Power Delivery Architecture with Isolated Differential Power Conversion for Data Centers,” TPEL16.
- M. Liu et al., “A 13.56 MHz Multiport-Wireless-Coupled (MWC) Battery Balancer with High Frequency Online Electrochemical Impedance Spectroscopy,” ECCE19.
- H. Schmidt and C. Siedle, “The charge equalizer-a new system to extend battery lifetime in photovoltaic systems, UPS and electric vehicles,” INTELEC93.
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